

Quad-Channel, 16-Bit, 1.25 GSPS Digital-to-Analog Converter (DAC)

Check for Samples: [DAC34H84](#)

FEATURES

- **Very Low Power: 1.4 W at 1.25 GSPS, Full Operating Conditions**
- **Multi-DAC Synchronization**
- **Selectable 2x, 4x, 8x, 16x Interpolation Filter**
 - **Stop-Band Attenuation > 90 dBc**
- **Flexible On-chip Complex Mixing**
 - **Two Independent Fine Mixers with 32-bit NCOs**
 - **Power Saving Coarse Mixers: $\pm n \times F_s/8$**
- **High Performance, Low Jitter Clock Multiplying PLL**
- **Digital I and Q Correction**
 - **Gain, Phase, Offset, and Group Delay Correction**
- **Digital Inverse Sinc Filters**
- **32-Bit DDR Flexible LVDS Input Data Bus**
 - **8 Sample Input FIFO**
 - **Supports Data Rates up to 625 MSPS**
 - **Data Pattern Checker**
 - **Parity Check**
- **Temperature Sensor**
- **Differential Scalable Output: 10mA to 30mA**
- **196-Ball, 12x12mm BGA (GREEN / Pb-Free)**

APPLICATIONS

- **Cellular Base Stations**
- **Diversity Transmit**
- **Wideband Communications**

DESCRIPTION

The DAC34H84 is a very low power, high dynamic range, quad-channel, 16-bit digital-to-analog converter (DAC) with a sample rate as high as 1.25 GSPS.

The device includes features that simplify the design of complex transmit architectures: 2x to 16x digital interpolation filters with over 90 dB of stop-band attenuation simplify the data interface and reconstruction filters. Independent complex mixers allow flexible carrier placement. A high-performance low jitter clock multiplier simplifies clocking of the device without significant impact on the dynamic range. The digital Quadrature Modulator Correction (QMC) enables complete IQ compensation for gain, offset, phase and group delay between channels in direct up-conversion applications.

Digital data is input to the device through a wide 32-bit LVDS data bus with on-chip termination. The wide bus allows the processing of very high bandwidth signals. The device includes a FIFO, data pattern checker and parity test to ease the input interface. The interface also allows full synchronization of multiple devices.

The device is characterized for operation over the entire industrial temperature range of -40°C to 85°C and is available in a 196-ball, 12x12mm, 0.8mm pitch BGA package.

The DAC34H84 very low power, high bandwidth support, superior crosstalk, high dynamic range and features are an ideal fit for next generation communication systems.

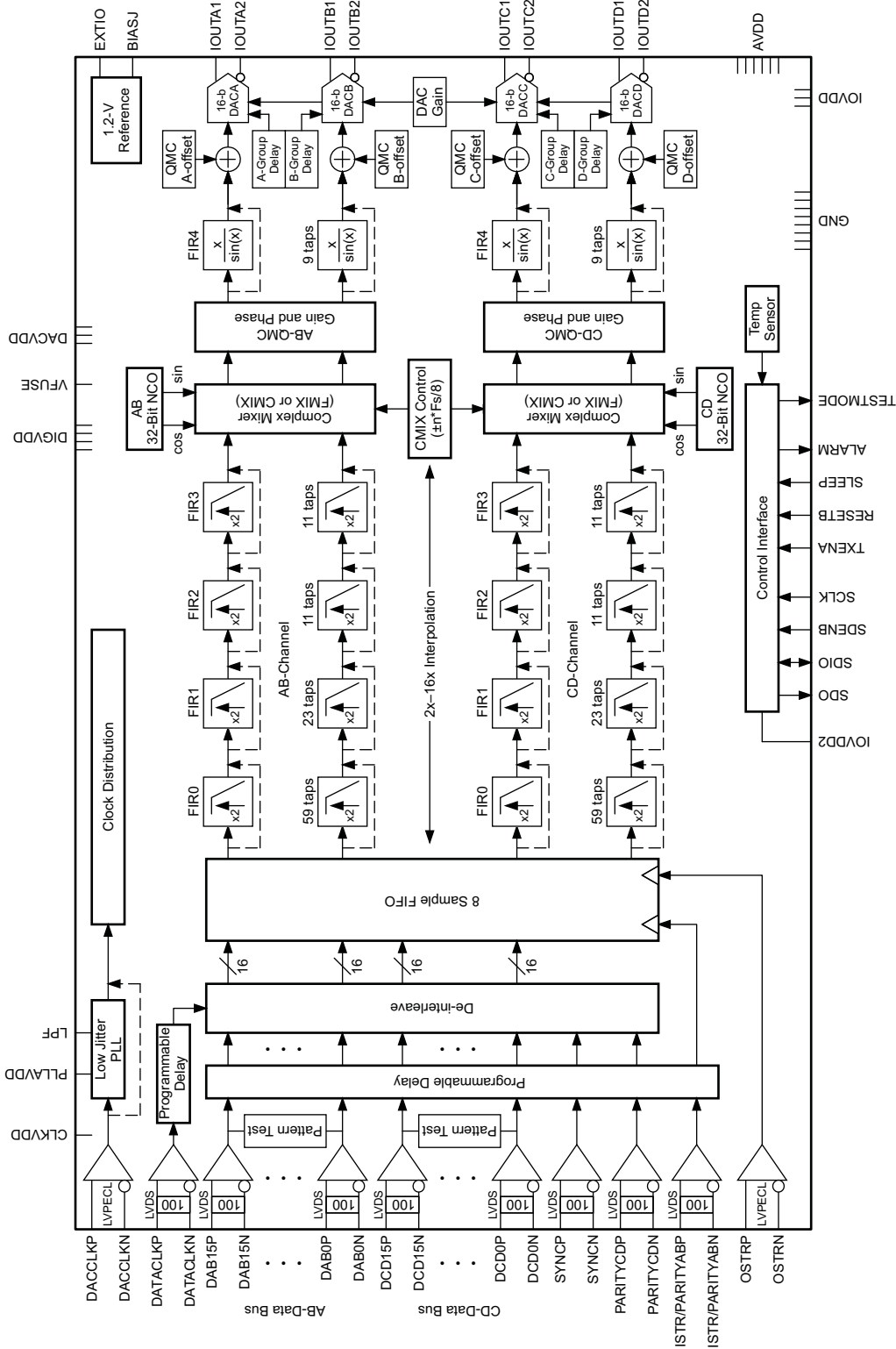
PRODUCT PREVIEW


Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

FUNCTIONAL BLOCK DIAGRAM

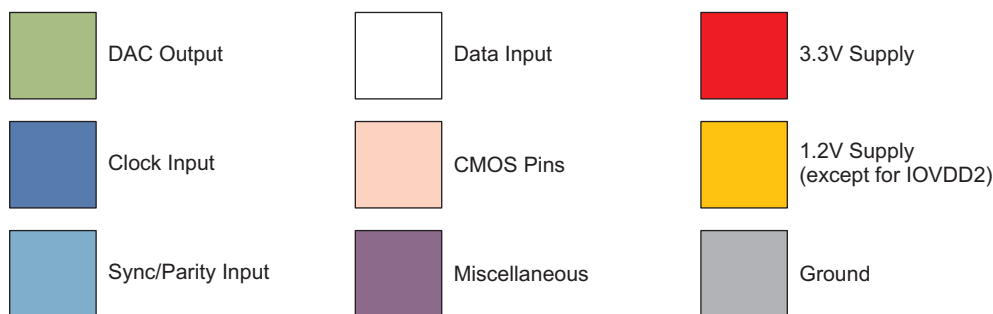


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PRODUCT PREVIEW

**PINOUT
ZAY Package
(Top View)**

	A	B	C	D	E	F	G	H	J	K	L	M	N	P
14	GND	IOUT AP	IOUT AN	GND	IOUT BN	IOUT BP	GND	GND	IOUT CP	IOUT CN	GND	IOUT DN	IOUT DP	GND
13	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND
12	DAC CLKP	GND	CLK VDD	LPF	GND	GND	EXTIO	BIASJ	GND	CLK VDD	IO VDD2	GND	ALARM	SDO
11	DAC CLKN	GND	PLL AVDD	PLL AVDD	AVDD	AVDD	AVDD	AVDD	AVDD	AVDD	TEST MODE	GND	SLEEP	SDIO
10	GND	GND	GND	AVDD	DAC VDD	DAC VDD	DAC VDD	DAC VDD	DAC VDD	DAC VDD	AVDD	GND	RESET B	SDENB
9	OSTR P	OSTR N	GND	DAC VDD	DAC VDD	GND	GND	GND	GND	DAC VDD	DAC VDD	GND	TXENA	SCLK
8	SYNC P	SYNC N	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	PARITY CDP	PARITY CDN
7	DAB 15P	DAB 15N	GND	VFUSE	DIG VDD	GND	GND	GND	GND	DIG VDD	VFUSE	GND	DCD 0P	DCD 0N
6	DAB 14P	DAB 14N	GND	IO VDD	DIG VDD	GND	GND	GND	GND	DIG VDD	IO VDD	GND	DCD 1P	DCD 1N
5	DAB 13P	DAB 13N	GND	IO VDD	DIG VDD	DIG VDD	IO VDD	IO VDD	DIG VDD	DIG VDD	IO VDD	GND	DCD 2P	DCD 2N
4	DAB 12P	DAB 12N	DAB 8P	DAB 6P	DAB 4P	DAB 2P	DAB 0P	DCD 15P	DCD 14P	DCD 12P	DCD 10P	DCD 8P	DCD 3P	DCD 3N
3	DAB 11P	DAB 11N	DAB 8N	DAB 6N	DAB 4N	DAB 2N	DAB 0N	DCD 15N	DCD 14N	DCD 12N	DCD 10N	DCD 8N	DCD 4P	DCD 4N
2	DAB 10P	DAB 10N	DAB 7P	DAB 5P	DAB 3P	DAB 1P	DATA CLKP	ISTR/PARITY ABP	DCD 13P	DCD 11P	DCD 9P	DCD 7P	DCD 5P	DCD 5N
1	DAB 9P	DAB 9N	DAB 7N	DAB 5N	DAB 3N	DAB 1N	DATA CLKN	ISTR/PARITY ABN	DCD 13N	DCD 11N	DCD 9N	DCD 7N	DCD 6P	DCD 6N



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PRODUCT PREVIEW

PIN FUNCTIONS

PIN		I/O	DESCRIPTION
NAME	NO.		
AVDD	D10, E11, F11, G11, H11, J11, K11, L10	I	Analog supply voltage. (3.3 V)
ALARM	N12	O	CMOS output for ALARM condition. The ALARM output functionality is defined through the <i>config7</i> register. Default polarity is active low, but can be changed to active high via <i>config0 alarm_out_pol</i> control bit.
BIASJ	H12	O	Full-scale output current bias. For 30mA full-scale output current, connect 1.28k Ω to ground. Change the full-scale output current through <i>coarse_dac(3:0)</i> in <i>config3</i> , <i>bit< 15:12></i>
CLKVDD	C12, K12	I	Internal clock buffer supply voltage. (1.2 V). It is recommended to isolate this supply from DIGVDD and DACVDD.
DAB[15..0]P	A7, A6, A5, A4, A3, A2, A1, C4, C2, D4, D2, E4, E2, F4, F2, G4	I	LVDS positive input data bits 0 through 15 for the AB-channel path. Internal 100 Ω termination resistor. Data format relative to DATACLKP/N clock is Double Data Rate (DDR). DAB15P is most significant data bit (MSB) DAB0P is least significant data bit (LSB) The order of the bus can be reversed via <i>config2 revbus</i> bit.
DAB[15..0]N	B7, B6, B5, B4, B3, B2, B1, C3, C1, D3, D1, E3, E1, F3, F1, G3	I	LVDS negative input data bits 0 through 15 for the AB-channel path. (See DAB[15:0]P description above)
DCD[15..0]P	H4, J4, J2, K4, K2, L4, L2, M4, M2, N1, N2, N3, N4, N5, N6, N7	I	LVDS positive input data bits 0 through 15 for the CD-channel path. Internal 100 Ω termination resistor. Data format relative to DATACLKP/N clock is Double Data Rate (DDR). DCD15P is most significant data bit (MSB) DCD0P is least significant data bit (LSB) The order of the bus can be reversed via <i>config2 revbus</i> bit.
DCD[15..0]N	H3, J3, J1, K3, K1, L3, L1, M3, M1, P1, P2, P3, P4, P5, P6, P7	I	LVDS negative input data bits 0 through 15 for the CD-channel path. (See DCD[15:0]P description above)
DACCLKP	A12	I	Positive external LVPECL clock input for DAC core with a self-bias.
DACCLKN	A11	I	Complementary external LVPECL clock input for DAC core. (see the DACCLKP description)
DACVDD	D9, E9, E10, F10, G10, H10, J10, K10, K9, L9	I	DAC core supply voltage. (1.2 V). It is recommended to isolate this supply from CLKVDD and DIGVDD.
DATACLKP	G2	I	LVDS positive input data clock. Internal 100 Ω termination resistor. Input data DAB[15:0]P/N and DCD[15:0]P/N are latched on both edges of DATACLKP/N (Double Data Rate).
DATACLKN	G1	I	LVDS negative input data clock. (See DATACLKP description)
DIGVDD	E5, E6, E7, F5, J5, K5, K6, K7	I	Digital supply voltage. (1.2 V). It is recommended to isolate this supply from CLKVDD and DACVDD.
EXTIO	G12	I/O	Used as external reference input when internal reference is disabled through <i>config27 extref_ena = '1'</i> . Used as internal reference output when <i>config27 extref_ena = '0'</i> (default). Requires a 0.1 μ F decoupling capacitor to AGND when used as reference output.
ISTRP/ PARITYABP	H2	I	LVDS input strobe positive input. Internal 100 Ω termination resistor. The main functions of this input are to sync the FIFO pointer, to provide a sync source to the digital blocks, and/or to act as a parity input for the AB-data bus. These functions are captured with the rising edge of DATACLKP/N. This signal should be edge-aligned with DAB[15:0]P/N and DCD[15:0]P/N. The PARITY, SYNC, and ISTR inputs are rotated to allow complete reversal of the data interface when setting the <i>rev_interface</i> bit in register <i>config1</i> .
ISTRN/ PARITYABN	H1	I	LVDS input strobe negative input. (See the ISTRP/PARITYABP description)

PIN FUNCTIONS (continued)

PIN		I/O	DESCRIPTION
NAME	NO.		
GND	A10, A13, A14, B10, B11, B12, B13, C5, C6, C7, C8, C9, C10, C13, D8, D13, D14, E8, E12, E13, F6, F7, F8, F9, F12, F13, G6, G7, G8, G9, G13, G14, H6, H7, H8, H9, H13, H14, J6, J7, J8, J9, J12, J13, K8, K13, L8, L13, L14, M5, M6, M7, M8, M9, M10, M11, M12, M13, N13, P13, P14	I	These pins are ground for all supplies.
IOUTAP	B14	O	A-Channel DAC current output. Connect directly to ground if unused.
IOUTAN	C14	O	A-Channel DAC complementary current output. Connect directly to ground if unused.
IOUTBP	F14	O	B-Channel DAC current output. Connect directly to ground if unused.
IOUTBN	E14	O	B-Channel DAC complementary current output. Connect directly to ground if unused.
IOUTCP	J14	O	C-Channel DAC current output. Connect directly to ground if unused.
IOUTCN	K14	O	C-Channel DAC complementary current output. Connect directly to ground if unused.
IOUTDP	N14	O	D-Channel DAC current output. Connect directly to ground if unused.
IOUTDN	M14	O	D-Channel DAC complementary current output. Connect directly to ground if unused.
IOVDD	D5, D6, G5, H5, L5, L6	I	Supply voltage for all LVDS I/O. (3.3 V)
IOVDD2	L12	I	Supply voltage for all CMOS I/O. (1.8 to 3.3V) This supply can range from 1.8V to 3.3V to change the input and output level of the CMOS I/O.
LPF	D12	I/O	PLL loop filter connection. If not using the clock multiplying PLL, the LPF pin can be left unconnected.
OSTRP	A9	I	Optional LVPECL output strobe positive input. This positive/negative pair is captured with the rising edge of DACCLKP/N. It is used to sync the divided-down clocks and FIFO output pointer in Dual Sync Source Mode. If unused it can be left unconnected.
OSTRN	B9	I	Optional LVPECL output strobe negative input. (See the OSTRP description)
PARITYCDP	N8	I	Optional LVDS positive input parity bit for the CD-data bus. The PARITYCDP/N LVDS pair has an internal 100 Ω termination resistor. If unused it can be left unconnected. The PARITY, SYNC, and ISTR inputs are rotated to allow complete reversal of the data interface when setting the <i>rev_interface</i> bit in register <i>config1</i> .
PARITYCDN	P8	I	Optional LVDS negative input parity bit for the CD-data bus.
PLLAVDD	C11, D11	I	PLL analog supply voltage. (3.3 V)
SCLK	P9	I	Serial interface clock. Internal pull-down.
SDENB	P10	I	Active low serial data enable, always an input to the DAC34H84. Internal pull-up.
SDIO	P11	1/O	Serial interface data. Bi-directional in 3-pin mode (default) and 4-pin mode. Internal pull-down.
SDO	P12	O	Uni-directional serial interface data in 4-pin mode. The SDO pin is tri-stated in 3-pin interface mode (default).
SLEEP	N11	I	Active high asynchronous hardware power-down input. Internal pull-down.
SYNCP	A8	I	LVDS SYNC positive input. Internal 100 Ω termination resistor. If unused it can be left unconnected. The PARITY, SYNC, and ISTR inputs are rotated to allow complete reversal of the data interface when setting the <i>rev_interface</i> bit in register <i>config1</i> .

PIN FUNCTIONS (continued)

PIN		I/O	DESCRIPTION
NAME	NO.		
SYNEN	B8	I	LVDS SYNC negative input.
RESETB	N10	I	Active low input for chip RESET. Internal pull-up.
TXENA	N9	I	Transmit enable active high input. Internal pull-down. To enable analog output data transmission, set <i>sif_txenable</i> in register <i>config3</i> to “1” or pull CMOS TXENA pin to high. To disable analog output, set <i>sif_txenable</i> to “0” and pull CMOS TXENA pin to low. The DAC output is forced to midscale.
TESTMODE	L11	I	This pin is used for factory testing. Internal pull-down. Leave unconnected for normal operation.
VFUSE	D7, L7	I	Digital supply voltage. This supply pin is also used for factory fuse programming. Connect to DACVDD for normal operation.

ORDERING INFORMATION⁽¹⁾

T _A	ORDER CODE	PACKAGE DRAWING/TYPE ⁽²⁾	TRANSPORT MEDIA	QUANTITY
-40°C to 85°C	DAC34H84IZAY	ZAY / 196 NFBGA	Tray	160
	DAC34H84IZAYR		Tape and Reel	1000

- (1) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or visit the device product folder at www.ti.com.
- (2) MSL Peak Temperature: Level-3-260C-168 HR

ABSOLUTE MAXIMUM RATINGS

over operating free-air temperature range (unless otherwise noted)⁽¹⁾

		VALUE		UNIT
		MIN	MAX	
Supply voltage range ⁽²⁾	DACVDD, DIGVDD, CLKVDD	-0.5	1.5	V
	VFUSE	-0.5	1.5	V
	IOVDD, IOVDD2	-0.5	4	V
	AVDD, PLLAVDD	-0.5	4	V
Pin voltage range ⁽²⁾	DAB[15..0]P/N, DCD[15..0]P/N, DATACLKP/N, ISTRP/N, PARITYCDP/N, SYNCN/N	-0.5	IOVDD + 0.5	V
	DACCLKP/N, OSTRP/N	-0.5	CLKVDD + 0.5	V
	ALARM, SDO, SDIO, SCLK, SDENB, SLEEP, RESETB, TESTMODE, TXENA	-0.5	IOVDD2 + 0.5	V
	IOUTAP/N, IOUTBP/N, IOUTCP/N, IOUTDP/N	-1.0	AVDD + 0.5	V
	EXTIO, BIASJ	-0.5	AVDD + 0.5	V
	LPF	-0.5	PLLAVDD + 0.5	V
Peak input current (any input)			20	mA
Peak total input current (all inputs)			-30	mA
Operating free-air temperature range, T _A : DAC34H84		-40	85	°C
Storage temperature range		-65	150	°C
Lead temperature 1,6 mm (1/16 inch) from the case for 10 seconds			260	°C

- (1) Stresses beyond those listed under absolute maximum ratings may cause permanent damage to the device. These are stress ratings only and functional operation of these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) Measured with respect to GND.

PRODUCT PREVIEW

THERMAL INFORMATION

THERMAL METRIC ⁽¹⁾		DAC34H84	
		BGA	
		(196 ball) PINS	
			UNITS
T _J	Maximum junction temperature	125	°C
θ _{JA}	Junction-to-ambient thermal resistance ⁽²⁾	37.6	°C/W
θ _{JCtop}	Junction-to-case (top) thermal resistance ⁽³⁾	6.8	
θ _{JCbot}	Junction-to-case (bottom) thermal resistance ⁽⁴⁾	N/A	
θ _{JB}	Junction-to-board thermal resistance ⁽⁵⁾	16.8	
ψ _{JT}	Junction-to-top characterization parameter ⁽⁶⁾	0.2	
ψ _{JB}	Junction-to-board characterization parameter ⁽⁷⁾	16.4	

- (1) For more information about traditional and new thermal metrics, see the *IC Package Thermal Metrics* application report, [SPRA953](#).
- (2) The junction-to-ambient thermal resistance under natural convection is obtained in a simulation on a JEDEC-standard, high-K board, as specified in JESD51-7, in an environment described in JESD51-2a.
- (3) The junction-to-case (top) thermal resistance is obtained by simulating a cold plate test on the package top. No specific JEDEC-standard test exists, but a close description can be found in the ANSI SEMI standard G30-88.
- (4) The junction-to-case (bottom) thermal resistance is obtained by simulating a cold plate test on the exposed (power) pad. No specific JEDEC standard test exists, but a close description can be found in the ANSI SEMI standard G30-88.
- (5) The junction-to-board thermal resistance is obtained by simulating in an environment with a ring cold plate fixture to control the PCB temperature, as described in JESD51-8.
- (6) The junction-to-top characterization parameter, ψ_{JT}, estimates the junction temperature of a device in a real system and is extracted from the simulation data for obtaining θ_{JA}, using a procedure described in JESD51-2a (sections 6 and 7).
- (7) The junction-to-board characterization parameter, ψ_{JB}, estimates the junction temperature of a device in a real system and is extracted from the simulation data for obtaining θ_{JA}, using a procedure described in JESD51-2a (sections 6 and 7).

ELECTRICAL CHARACTERISTICS – DC SPECIFICATIONS⁽¹⁾

over recommended operating free-air temperature range, nominal supplies, $I_{OUT_{FS}} = 20\text{mA}$ (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
Resolution			16			Bits
DC ACCURACY						
DNL	Differential nonlinearity	1 LSB = $I_{OUT_{FS}}/2^{16}$	±2			LSB
INL	Integral nonlinearity		±4			LSB
ANALOG OUTPUT						
Coarse gain linearity			±0.04			LSB
Offset error		Mid code offset	±0.00 1			%FSR
Gain error		With external reference	±2			%FSR
		With internal reference	±2			%FSR
Gain mismatch		With internal reference	±2			%FSR
Full scale output current			10	20	30	mA
Output compliance range			-0.5		0.6	V
Output resistance			300			kΩ
Output capacitance			5			pF
REFERENCE OUTPUT						
V_{REF}	Reference output voltage		1.2			V
	Reference output current ⁽²⁾		100			nA
REFERENCE INPUT						
V_{EXTIO}	Input voltage range	External Reference Mode	0.6	1.2	1.25	V
	Input resistance		1			MΩ
	Small signal bandwidth		472			kHz
	Input capacitance		100			pF
TEMPERATURE COEFFICIENTS						
Offset drift			±1			ppm/°C
Gain drift		with external reference	±15			ppm/°C
		with internal reference	±30			ppm/°C
Reference voltage drift			±8			ppm/°C
POWER SUPPLY						
AVDD, IOVDD, PLLAVDD			3.14	3.3	3.46	V
CLKVDD, DACVDD, DIGVDD			1.14	1.2	1.26	V
IOVDD2			1.71	3.3	3.45	V
PSRR	Power supply rejection ratio	DC tested	±0.25			%FSR/V
POWER CONSUMPTION						
$I_{(AVDD)}$	Analog supply current ⁽³⁾	MODE 1 $f_{DAC} = 1.25\text{GSPS}$, 2x interpolation, Mixer on, QMC on, invsinc on, PLL enabled, 20mA FS output, IF = 200MHz	132			mA
$I_{(DIGVDD)}$	Digital supply current		677			mA
$I_{(DACVDD)}$	DAC supply current		46			mA
$I_{(CLKVDD)}$	Clock supply current		93			mA
P	Power dissipation		1414			mW
$I_{(AVDD)}$	Analog supply current ⁽³⁾	MODE 2 $f_{DAC} = 1.25\text{GSPS}$, 2x interpolation, Mixer on, QMC on, invsinc on, PLL disabled, 20mA FS output, IF = 200MHz	117			mA
$I_{(DIGVDD)}$	Digital supply current		677			mA
$I_{(DACVDD)}$	DAC supply current		46			mA
$I_{(CLKVDD)}$	Clock supply current		72			mA
P	Power dissipation		1340			mW

(1) Measured differentially across IOUTP/N with 25 Ω each to GND.

(2) Use an external buffer amplifier with high impedance input to drive any external load.

(3) Includes AVDD, PLLAVDD, and IOVDD

ELECTRICAL CHARACTERISTICS – DC SPECIFICATIONS⁽¹⁾ (continued)

 over recommended operating free-air temperature range, nominal supplies, IOUT_{FS} = 20mA (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
I _(AVDD)	Analog supply current ⁽³⁾	MODE 3 f _{DAC} = 625MSPS, 2x interpolation, Mixer on, QMC on, invsinc off, PLL disabled, 20mA FS output, IF = 200MHz		117		mA
I _(DIGVDD)	Digital supply current			355		mA
I _(DACVDD)	DAC supply current			27		mA
I _(CLKVDD)	Clock supply current			41		mA
P	Power dissipation			893		mW
I _(AVDD)	Analog supply current ⁽³⁾	MODE 4 f _{DAC} = 1.25GSPS, 2x interpolation, Mixer on, QMC on, invsinc on, PLL enabled, I/Q output sleep, IF = 200MHz,		41		mA
I _(DIGVDD)	Digital supply current			677		mA
I _(DACVDD)	DAC supply current			49		mA
I _(CLKVDD)	Clock supply current			93		mA
P	Power dissipation			1118		mW
I _(AVDD)	Analog supply current ⁽³⁾	Mode 5 Power-Down mode: No clock, DAC on sleep mode (clock receiver sleep), I/Q output sleep, static data pattern		27		mA
I _(DIGVDD)	Digital supply current			67		mA
I _(DACVDD)	DAC supply current			4		mA
I _(CLKVDD)	Clock supply current			9		mA
P	Power dissipation			185		mW
I _(AVDD)	Analog supply current ⁽³⁾	Mode 6 f _{DAC} = 1GSPS, 2x interpolation, Mixer off, QMC off, invsinc off, PLL enabled, 20mA FS output, IF = 200MHz		132		mA
I _(DIGVDD)	Digital supply current			350		mA
I _(DACVDD)	DAC supply current			43		mA
I _(CLKVDD)	Clock supply current			84		mA
P	Power dissipation			1008		mW
I _(AVDD)	Analog supply current ⁽³⁾	Mode 7 f _{DAC} = 1GSPS, 2x interpolation, Mixer off, QMC off, invsinc off, PLL disabled, 20mA FS output, IF = 200MHz		118		mA
I _(DIGVDD)	Digital supply current			354		mA
I _(DACVDD)	DAC supply current			43		mA
I _(CLKVDD)	Clock supply current			61		mA
P	Power dissipation			940		mW
Operating Range			-40	25	85	°C

ELECTRICAL CHARACTERISTICS – DIGITAL SPECIFICATIONS

over operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
LVDS INPUTS: D[15:0]P/N, DATACLKP/N, ISSTRP/N, SYNCNP/N, PARITYCDP/N⁽¹⁾						
V _{A,B+}	Logic high differential input voltage threshold		250	400		mV
V _{A,B-}	Logic low differential input voltage threshold		-250	-400		mV
V _{COM}	Input Common Mode		1.075	1.2		V
Z _T	Internal termination			110		Ω
C _L	LVDS Input capacitance			2		pF
f _{INTERL}	Interleaved LVDS data transfer rate				1250	MSPS
f _{DATA}	Input data rate				625	MSPS
CLOCK INPUT (DACCLKP/N)						
	Duty cycle		40%		60%	
	Differential voltage ⁽²⁾		0.4	1.0		V
	DACCLKP/N Input Frequency				1250	MHz
OUTPUT STROBE (OSTRP/N)						
f _{OSTR}	Frequency	f _{OSTR} = f _{DACCLK} / (n x 8 x Interp) where n is any positive integer f _{DACCLK} is DACCLK frequency in MHz			f _{DACCLK} / (8 x interp)	MHz
	Duty cycle			50%		
	Differential voltage		0.4	1.0		V
CMOS INTERFACE: ALARM, SDO, SDIO, SCLK, SDENB, SLEEP, RESETB, TXENA						
V _{IH}	High-level input voltage		0.7 x IOVDD			V
V _{IL}	Low-level input voltage				0.3 x IOVDD	V
I _{IH}	High-level input current		-40		40	μA
I _{IL}	Low-level input current		-40		40	μA
C _I	CMOS Input capacitance			2		pF
V _{OH}	ALARM, SDO, SDIO	I _{load} = -100 μA	IOVDD - 0.2			V
		I _{load} = -2 mA	0.8 x IOVDD			V
V _{OL}	ALARM, SDO, SDIO	I _{load} = 100 μA			0.2	V
		I _{load} = 2 mA			0.5	V
DIGITAL INPUT TIMING SPECIFICATIONS						
Timing LVDS inputs: D[15:0]P/N, ISTRP/N, SYNCNP/N, PARITYCDP/N, double edge latching						
t _{s(DATA)}	Setup time, DAB[15:0]P/N, DCD[15:0]P/N, ISTRP/N, SYNCNP/N and PARITYCDP/N, valid to either edge of DATACLKP/N	ISTRP/N and SYNCNP/N reset latched only on rising edge of DATACLKP/N.	200			ps
t _{h(DATA)}	Hold time, D[15:0]P/N, ISTRP/N, SYNCNP/N and PARITYCDP/N, valid after either edge of DATACLKP/N	ISTRP/N and SYNCNP/N reset latched only on rising edge of DATACLKP/N.	200			ps
t _(ISTR_SYNC)	ISTRP/N and SYNCNP/N pulse width	f _{DATACLK} is DATACLK frequency in MHz	1/2f _{DATACLK}			ns
t _(align)	Maximum offset between DATACLKP/N and DACCLKP/N rising edges	FIFO Bypass Mode only			±300	ps

(1) See LVDS INPUTS section for terminology.

(2) Driving the clock input with a differential voltage lower than 1 V will result in degraded performance.

ELECTRICAL CHARACTERISTICS – DIGITAL SPECIFICATIONS (continued)

over operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
TIMING OUTPUT STROBE INPUT: DACCLKP/N rising edge LATCHING⁽³⁾						
$t_{s(OSTR)}$	Setup time, OSTRP/N valid to rising edge of DACCLKP/N		200			ps
$t_{h(OSTR)}$	Hold time, OSTRP/N valid after rising edge of DACCLKP/N		200			ps
TIMING SYNC INPUT: DACCLKP/N rising edge LATCHING⁽⁴⁾						
$t_{s(SYNC_PLL)}$	Setup time, SYNC/N valid to rising edge of DACCLKP/N			200		ps
$t_{h(SYNC_PLL)}$	Hold time, SYNC/N valid after rising edge of DACCLKP/N			300		ps
TIMING SERIAL PORT						
$t_{s(SDENB)}$	Setup time, SDENB to rising edge of SCLK		20			ns
$t_{s(SDIO)}$	Setup time, SDIO valid to rising edge of SCLK		10			ns
$t_{h(SDIO)}$	Hold time, SDIO valid to rising edge of SCLK		5			ns
$t_{(SCLK)}$	Period of SCLK	Register <i>config6</i> read (temperature sensor read)	1			μs
		All other registers	100			ns
$t_{d(Data)}$	Data output delay after falling edge of SCLK			10		ns
t_{RESET}	Minimum RESETB pulsewidth			25		ns

(3) OSTR is required in Dual Sync Source mode. In order to minimize the skew it is recommended to use the same clock distribution device such as Texas Instruments CDCE62005 to provide the DACCLK and OSTR signals to all the DAC34H84 devices in the system. Swap the polarity of the DACCLK outputs with respect to the OSTR ones to establish proper phase relationship.

(4) SYNC is required to synchronize the PLL circuit in multiple devices. The SYNC signal must meet the timing relationship with respect to the reference clock (DACCLKP/N) of the on-chip PLL circuit.

ELECTRICAL CHARACTERISTICS – AC SPECIFICATIONS

over recommended operating free-air temperature range, nominal supplies, $I_{OUT_{FS}} = 20\text{mA}$ (unless otherwise noted)

PARAMETER		TEST CONDITIONS / COMMENTS	MIN	TYP	MAX	UNIT
ANALOG OUTPUT⁽¹⁾						
f_{DAC}	Maximum DAC rate		1250			MSPS
$t_{s(DAC)}$	Output settling time to 0.1%	Transition: Code 0x0000 to 0xFFFF		10		ns
t_{pd}	Output propagation delay	DAC outputs are updated on the falling edge of DAC clock. Does not include Digital Latency (see below).		2		ns
$t_{r(IOUT)}$	Output rise time 10% to 90%			220		ps
$t_{f(IOUT)}$	Output fall time 90% to 10%			220		ps
Digital Latency		No interpolation, FIFO off, Mixer off, QMC off, Inverse sinc off		128		DAC clock cycles
		2x Interpolation		216		
		4x Interpolation		376		
		8x Interpolation		726		
		16x Interpolation		1427		
		Fine Mixer		24		
		QMC		16		
Power-up Time		DAC Wake-up Time from Deep Sleep	IOUT current settling to 1% of $I_{OUT_{FS}}$		90	μs
		DAC Deep Sleep Time	IOUT current settling to less than 1% of $I_{OUT_{FS}}$		90	
AC PERFORMANCE⁽²⁾						
SFDR	Spurious free dynamic range (0 to $f_{DAC}/2$) Tone at 0 dBFS	$f_{DAC} = 1.25\text{ GSPS}$, $f_{OUT} = 20\text{ MHz}$		82		dBc
		$f_{DAC} = 1.25\text{ GSPS}$, $f_{OUT} = 50\text{ MHz}$		77		
		$f_{DAC} = 1.25\text{ GSPS}$, $f_{OUT} = 70\text{ MHz}$		72		
IMD3	Third-order two-tone intermodulation distortion Each tone at -12 dBFS	$f_{DAC} = 1.25\text{ MSPS}$, $f_{OUT} = 30 \pm 0.5\text{ MHz}$		81		dBc
		$f_{DAC} = 1.25\text{ GSPS}$, $f_{OUT} = 50 \pm 0.5\text{ MHz}$		79		
		$f_{DAC} = 1.25\text{ GSPS}$, $f_{OUT} = 100 \pm 0.5\text{ MHz}$		77.5		
NSD	Noise Spectral Density ⁽³⁾ Tone at 0dBFS	$f_{DAC} = 1.25\text{ GSPS}$, $f_{OUT} = 10\text{ MHz}$		160		dBc/Hz
		$f_{DAC} = 1.25\text{ GSPS}$, $f_{OUT} = 80\text{ MHz}$		155		
ACLR ⁽³⁾	Adjacent channel leakage ratio, single carrier	$f_{DAC} = 1.2288\text{ GSPS}$, $f_{OUT} = 30.72\text{ MHz}$		77		dBc
		$f_{DAC} = 1.2288\text{ GSPS}$, $f_{OUT} = 153.6\text{ MHz}$		74		
	Alternate channel leakage ratio, single carrier	$f_{DAC} = 1.2288\text{ GSPS}$, $f_{OUT} = 30.72\text{ MHz}$		82		
		$f_{DAC} = 1.2288\text{ GSPS}$, $f_{OUT} = 153.6\text{ MHz}$		80		
Channel Isolation		$f_{DAC} = 1.25\text{ GSPS}$, $f_{OUT} = 10\text{ MHz}$		84		dBc

(1) Measured single ended into $50\ \Omega$ load.

(2) 4:1 transformer output termination, $50\ \Omega$ doubly terminated load

(3) Single carrier, W-CDMA with 3.84 MHz BW, 5-MHz spacing, centered at IF, PAR = 12dB. TESTMODEL 1, 10 ms

DEFINITION OF SPECIFICATIONS

Adjacent Carrier Leakage Ratio (ACLR): Defined for a 3.84Mcps 3GPP W-CDMA input signal measured in a 3.84MHz bandwidth at a 5MHz offset from the carrier with a 12dB peak-to-average ratio.

Analog and Digital Power Supply Rejection Ratio (APSSR, DPSSR): Defined as the percentage error in the ratio of the delta IOUT and delta supply voltage normalized with respect to the ideal IOUT current.

Differential Nonlinearity (DNL): Defined as the variation in analog output associated with an ideal 1 LSB change in the digital input code.

Gain Drift: Defined as the maximum change in gain, in terms of ppm of full-scale range (FSR) per $^{\circ}\text{C}$, from the value at ambient (25°C) to values over the full operating temperature range.

Gain Error: Defined as the percentage error (in FSR%) for the ratio between the measured full-scale output current and the ideal full-scale output current.

Integral Nonlinearity (INL): Defined as the maximum deviation of the actual analog output from the ideal output, determined by a straight line drawn from zero scale to full scale.

Intermodulation Distortion (IMD3): The two-tone IMD3 is defined as the ratio (in dBc) of the 3rd-order intermodulation distortion product to either fundamental output tone.

Offset Drift: Defined as the maximum change in DC offset, in terms of ppm of full-scale range (FSR) per °C, from the value at ambient (25°C) to values over the full operating temperature range.

Offset Error: Defined as the percentage error (in FSR%) for the ratio between the measured mid-scale output current and the ideal mid-scale output current.

Output Compliance Range: Defined as the minimum and maximum allowable voltage at the output of the current-output DAC. Exceeding this limit may result reduced reliability of the device or adversely affecting distortion performance.

Reference Voltage Drift: Defined as the maximum change of the reference voltage in ppm per degree Celsius from value at ambient (25°C) to values over the full operating temperature range.

Spurious Free Dynamic Range (SFDR): Defined as the difference (in dBc) between the peak amplitude of the output signal and the peak spurious signal within the first Nyquist zone.

Noise Spectral Density (NSD): Defined as the difference of power (in dBc) between the output tone signal power and the noise floor of 1Hz bandwidth within the first Nyquist zone.

SERIAL INTERFACE

The serial port of the DAC34H84 is a flexible serial interface which communicates with industry standard microprocessors and microcontrollers. The interface provides read/write access to all registers used to define the operating modes of DAC34H84. It is compatible with most synchronous transfer formats and can be configured as a 3 or 4 pin interface by *sif4_ena* in register *config2*. In both configurations, SCLK is the serial interface input clock and SDENB is serial interface enable. For 3 pin configuration, SDIO is a bidirectional pin for both data in and data out. For 4 pin configuration, SDIO is bidirectional and SDO is data out only. Data is input into the device with the rising edge of SCLK. Data is output from the device on the falling edge of SCLK.

Each read/write operation is framed by signal SDENB (Serial Data Enable Bar) asserted low. The first frame byte is the instruction cycle which identifies the following data transfer cycle as read or write as well as the 7-bit address to be accessed. [Table 1](#) indicates the function of each bit in the instruction cycle and is followed by a detailed description of each bit. The data transfer cycle consists of two bytes

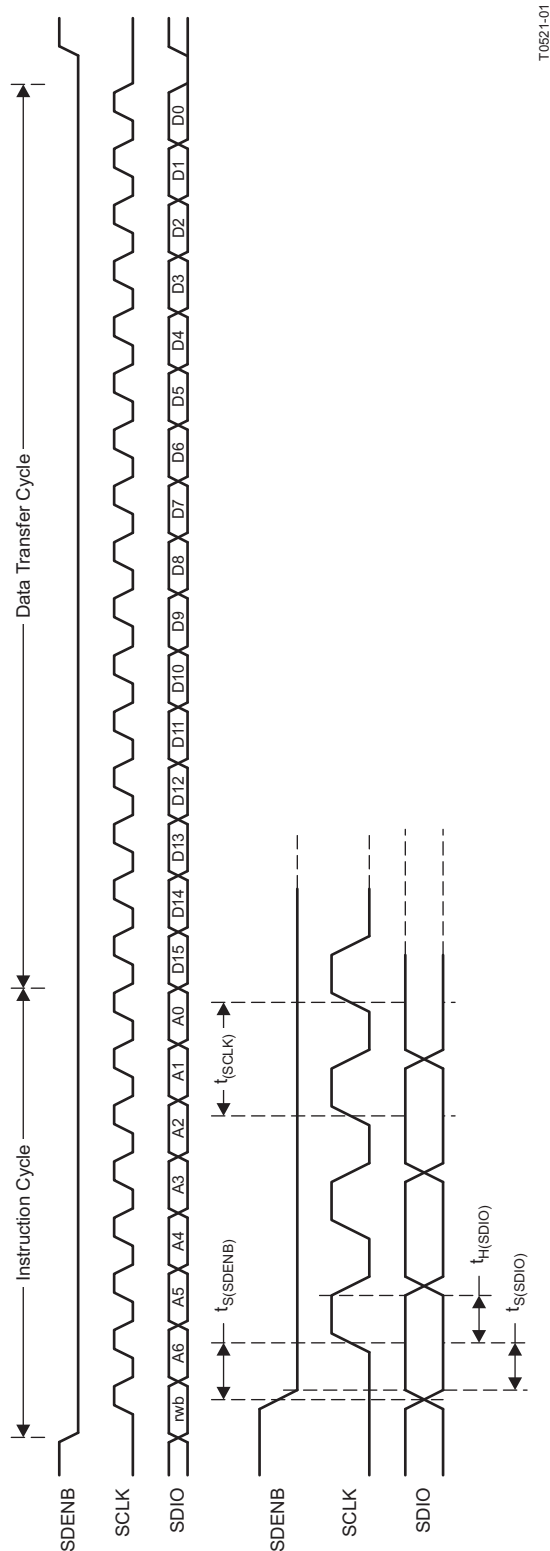
Table 1. Instruction Byte of the Serial Interface

	MSB							LSB
Bit	7	6	5	4	3	2	1	0
Description	R/W	A6	A5	A4	A3	A2	A1	A0

R/W Identifies the following data transfer cycle as a read or write operation. A high indicates a read operation from DAC34H84 and a low indicates a write operation to DAC34H84.

[A6 : A0] Identifies the address of the register to be accessed during the read or write operation.

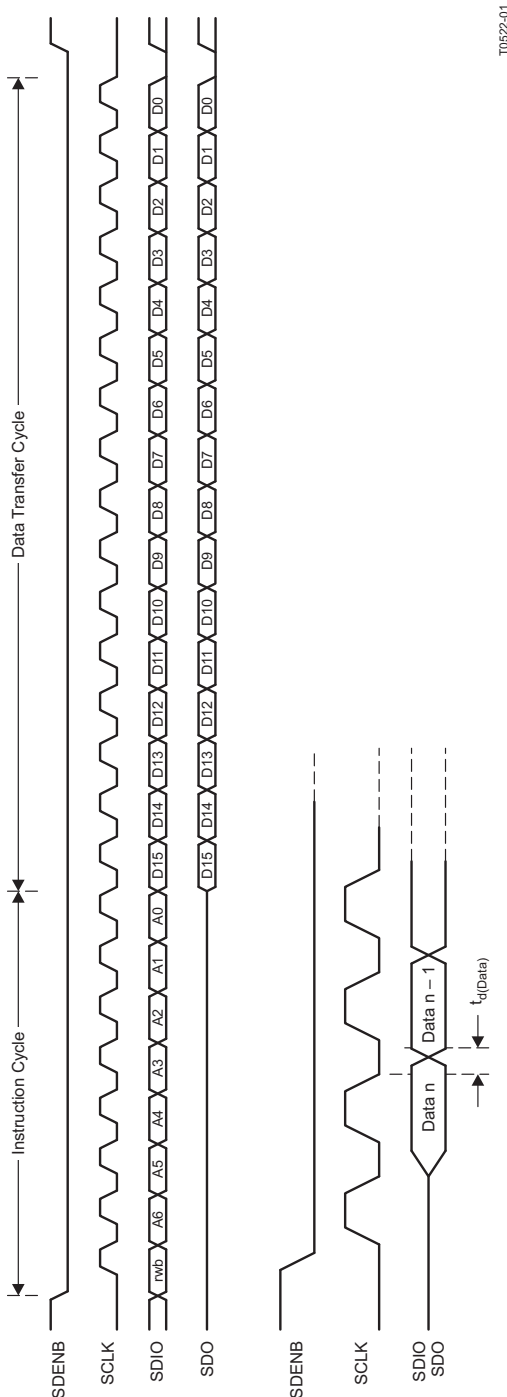
Figure 1 shows the serial interface timing diagram for a DAC34H84 write operation. SCLK is the serial interface clock input to DAC34H84. Serial data enable SDENB is an active low input to DAC34H84. SDIO is serial data in. Input data to DAC34H84 is clocked on the rising edges of SCLK.



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Figure 1. Serial Interface Write Timing Diagram

Figure 2 shows the serial interface timing diagram for a DAC34H84 read operation. SCLK is the serial interface clock input to DAC34H84. Serial data enable SDENB is an active low input to DAC34H84. SDIO is serial data in during the instruction cycle. In 3 pin configuration, SDIO is data out from the DAC34H84 during the data transfer cycle, while SDO is in a high-impedance state. In 4 pin configuration, both SDIO and SDO are data out from the DAC34H84 during the data transfer cycle. At the end of the data transfer, SDIO and SDO will output low on the final falling edge of SCLK until the rising edge of SDENB when it will 3-state.



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Figure 2. Serial Interface Read Timing Diagram

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Table 2. Register Map

Name	Address	Default	(MSB) Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	(LSB) Bit 0			
config0	0x00	0x049C	qmc_offsetAB_ena	qmc_offsetCD_ena	qmc_corrAB_ena	qmc_corrCD_ena	interp(3:0)				fifo_ena	reserved	reserved	alarm_out_ena	alarm_out_pol	clkdiv_sync_ena	invsincAB_ena	invsincCD_ena			
config1	0x01	0x050E	iotest_ena	reserved	reserved	64cnt_ena	oddeven_parity	single_parity_ena	dual_parity_ena	rev_interface	dacA_complement	dacB_complement	dacC_complement	dacD_complement	alarm_2away_ena	alarm_1away_ena	alarm_collision_ena	reserved			
config2	0x02	0x7000	reserved	dacclk_gone_ena	dataclk_gone_ena	collision_gone_ena	clkmon_sync_ena	reserved	reserved	reserved	sif4_ena	mixer_ena	mixer_gain	nco_ena	revbus	reserved	twos	reserved			
config3	0x03	0xF000	coarse_dac(3:0)				reserved				reserved						sif_txenable				
config4	0x04	NA	iotest_results(15:0)																		
config5	0x05	0x0000	alarm_from_zerochk	reserved	alarms_from_fifo(2:0)			alarm_dacclk_gone	alarm_dataclk_gone	clock_gone	alarm_from_iotest	reserved	alarm_from_pll	alarm_Aparity	alarm_Bparity	alarm_Cparity	alarm_Dparity	reserved			
config6	0x06	NA	tmpdata(7:0)							reserved										reserved	reserved
config7	0x07	0xFFFF	alarms_mask(15:0)																		
config8	0x08	0x0000	reserved	reserved	reserved	qmc_offsetA(12:0)															
config9	0x09	0x0800	fifo_offset(2:0)			qmc_offsetB(12:0)															
config10	0x0A	0x0000	reserved	reserved	reserved	qmc_offsetC(12:0)															
config11	0x0B	0x0000	reserved	reserved	reserved	qmc_offsetD(12:0)															
config12	0x0C	0x0400	reserved	reserved	reserved	reserved	reserved	qmc_gainA(10:0)													
config13	0x0D	0x0400	cmix(3:0)				reserved	qmc_gainB(10:0)													
config14	0x0E	0x0400	reserved	reserved	reserved	reserved	reserved	qmc_gainC(10:0)													
config15	0x0F	0x0400	output_delayAB(1:0)	output_delayDC(1:0)	reserved	qmc_gainD(10:0)															
config16	0x10	0x0000	reserved	reserved	reserved	reserved	qmc_phaseAB(11:0)														
config17	0x11	0x0000	reserved	reserved	reserved	reserved	qmc_phaseCD(11:0)														
config18	0x12	0x0000	phase_offsetAB(15:0)																		
config19	0x13	0x0000	phase_offsetCD(15:0)																		
config20	0x14	0x0000	phase_addAB(15:0)																		
config21	0x15	0x0000	phase_addAB(31:16)																		
config22	0x16	0x0000	phase_addCD(15:0)																		
config23	0x17	0x0000	phase_addCD(31:16)																		
config24	0x18	NA	reserved			pll_reset	pll_ndivsync_ena	pll_ena	reserved			pll_cp(1:0)	pll_p(2:0)			pll_lfvolt(2:0)					
config25	0x19	0x0440	pll_m(7:0)							pll_n(3:0)				pll_vcoitune(2:0)			reserved				
config26	0x1A	0x0020	pll_vco(5:0)						reserved	reserved	bias_sleep	tsense_sleep	pll_sleep	clkrecv_sleep	sleepA	sleepB	sleepC	sleepC			
config27	0x1B	0x0000	extref_ena	reserved	reserved	reserved	reserved	reserved	reserved	reserved	reserved	reserved	reserved								
config28	0x1C	0x0000	reserved									reserved									
config29	0x1D	0x0000	reserved									reserved									
config30	0x1E	0x1111	syncsel_qmoffsetAB(4:0)				syncsel_qmoffsetCD(4:0)				syncsel_qmcorrAB(4:0)				syncsel_qmcorrCD(4:0)						
config31	0x1F	0x1140	syncsel_mixerAB(4:0)				syncsel_mixerCD(4:0)				syncsel_nco(4:0)				syncsel_dataformatter	sif_sync	reserve				

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Table 2. Register Map (continued)

Name	Address	Default	(MSB) Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	(LSB) Bit 0
config32	0x20	0x2400	syncsel_fifo(4:0)				syncsel_fifoout(4:0)				reserved							clkdiv_ sync_sel
config33	0x21	0x0000	reserved															
config34	0x22	0x1B1B	pathA_in_set(1:0)		pathB_in_set(1:0)		pathC_in_set(1:0)		pathD_in_set(1:0)		DACA_in_set(1:0)		DACB_in_set(1:0)		DACC_in_set(1:0)		DACD_in_set(1:0)	
config35	0x23	0xFFFF	sleep_cntl(15:0)															
config36	0x24	0x0000	datadly(2:0)		clkdly(2:0)				reserved									
config37	0x25	0x7A7A	iotest_pattern0															
config38	0x26	0xB6B6	iotest_pattern1															
config39	0x27	0xEAEA	iotest_pattern2															
config40	0x28	0x4545	iotest_pattern3															
config41	0x29	0x1A1A	iotest_pattern4															
config42	0x2A	0x1616	iotest_pattern5															
config43	0x2B	0xAAAA	iotest_pattern6															
config44	0x2C	0xC6C6	iotest_pattern7															
config45	0x2D	0x0000	fifoalarm_ resync	ostrtodig_ sel	ramp_ena		reserved											sifdac_ena
config46	0x2E	0x0000	grp_delayA(7:0)								grp_delayB(7:0)							
config47	0x2F	0x0000	grp_delayC(7:0)								grp_delayD(7:0)							
config48	0x30	0x0000	sifdac(15:0)															
version	0x7F	0x5409	reserved						reserved	reserved	reserved	reserved	deviceid(1:0)			versionid(2:0)		

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REGISTER DESCRIPTIONS

Register name: config0 – Address: 0x00, Default: 0x049C

Register Name	Address	Bit	Name	Function	Default Value	
config0	0x00	15	qmc_offsetAB_ena	When set, the digital Quadrature Modulator Correction (QMC) offset correction for the AB data path is enabled.	0	
		14	qmc_offsetCD_ena	When set, the digital Quadrature Modulator Correction (QMC) offset correction for the CD data path is enabled.	0	
		13	qmc_corrAB_ena	When set, the QMC phase and gain correction circuitry for the AB data path is enabled.	0	
		12	qmc_corrCD_ena	When set, the QMC phase and gain correction circuitry for the CD data path is enabled.	0	
		11:8	interp(3:0)	These bits define the interpolation factor	0100	
				interp	Interpolation Factor	
				0000	1x	
				0001	2x	
				0010	4x	
				0100	8x	
				1000	16x	
		7	fifo_ena	When set, the FIFO is enabled. When the FIFO is disabled DACCLKP/N and DATACLKP/N must be aligned to within $t_{(align)}$ (not recommended).	1	
		6	Reserved	Reserved for factory use.	0	
5	Reserved	Reserved for factory use.	0			
4	alarm_out_ena	When set, the ALARM pin becomes an output. When cleared, the ALARM pin is 3-stated.	1			
3	alarm_out_pol	This bit changes the polarity of the ALARM signal. 0: Negative logic 1: Positive logic	1			
2	clkdiv_sync_ena	When set, enables the syncing of the clock divider using the sync source selected by register <i>config19</i> .	1			
1	invsincAB_ena	When set, the inverse sinc filter for the AB data path is enabled.	0			
0	invsincCD_ena	When set, the inverse sinc filter for the CD data path is enabled.	0			

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Register name: config1 – Address: 0x01, Default: 0x050E

Register Name	Address	Bit	Name	Function	Default Value
config1	0x01	15	iotest_ena	When set, enables the data pattern checker test. The outputs are deactivated regardless of the state of TXENA and sif_txenable.	0
		14	Reserved	Reserved for factory use.	0
		13	Reserved	Reserved for factory use.	0
		12	64cnt_ena	When set, enables resetting of the alarms after 64 good samples with the goal of removing unnecessary errors. For instance, when checking setup/hold through the pattern checker test, there may initially be errors. Setting this bit removes the need for a SIF write to clear the alarm register.	0
		11	oddeven_parity	Selects between odd and even parity check 0: Even parity 1: Odd parity	0
		10	single_parity_ena	When set, enables parity checking of each input word using the 1 PARITYP/N parity input. It should match the oddeven_parity register setting.	1
		9	dual_parity_ena	When set, enables parity checking using the ISTR signal to 0 source the parity bit. The parity bit should match the oddeven_parity register setting.	0
		8	rev_interface	When set, the PARITY, SYNC, and ISTR inputs are rotated to allow complete reversal of the data interface when setting the rev_interface bit. When <i>rev_interface</i> = "1", the following changes occurs 1. SYNCP/N becomes ISTRP/N 2. ARITYP/N becomes SYNCP/N 3. ISTRP/N becomes PARITYP/N	1
		7	dacA_complement	When set, the DACA output is complemented. This allows to effectively change the + and – designations of the LVDS data lines.	0
		6	dacB_complement	When set, the DACB output is complemented. This allows to effectively change the + and – designations of the LVDS data lines.	0
		5	dacC_complement	When set, the DACC output is complemented. This allows to effectively change the + and – designations of the LVDS data lines.	0
		4	dacD_complement	When set, the DACD output is complemented. This allows to effectively change the + and – designations of the LVDS data lines.	0
		3	alarm_2away_ena	When set, the alarm from the FIFO indicating the write and read pointers being 2 away is enabled.	1
		2	alarm_1away_ena	When set, the alarm from the FIFO indicating the write and read pointers being 1 away is enabled.	1
1	alarm_collision_ena	When set, the alarm from the FIFO indicating a collision between the write and read pointers is enabled.	1		
0	Reserved	Reserved for factory use.	0		

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Register name: config2 – Address: 0x02, Default: 0x7000

Register Name	Address	Bit	Name	Function	Default Value
config2	0x02	15	Reserved	Reserved for factory use.	0
		14	dacclkgone_ena	When set, the DACCLK-gone signal from the clock monitor circuit can be used to shut off the DAC outputs.	1
		13	dataclkgone_ena	When set, the DATACLK-gone signal from the clock monitor circuit can be used to shut off the DAC outputs.	1
		12	collisiongone_ena	When set, the FIFO collision alarms can be used to shut off the DAC outputs.	1
		11	clkmomsync_ena	When set, the clock monitor circuit is synced with every rising edge of the syncs chosen for the FIFO read and write pointers. See config32.	0
		10	Reserved	Reserved for factory use.	0
		9	Reserved	Reserved for factory use.	0
		8	Reserved	Reserved for factory use.	0
		7	sif4_ena	When set, the serial interface (SIF) is a 4 bit interface, otherwise it is a 3 bit interface.	0
		6	mixer_ena	When set, the mixer block is enabled.	0
		5	mixer_gain	When set, a 6dB gain is added to the mixer output.	0
		4	nco_ena	When set, the NCO is enabled. This is not required for coarse mixing.	0
		3	revbus	When set, the input bits for the data bus are reversed. MSB becomes LSB.	0
		2	Reserved	Reserved for factory use.	0
1	twos	When set, the input data format is expected to be 2's complement. When cleared, the input is expected to be offset-binary.	0		
0	Reserved	Reserved for factory use.	0		

Register name: config3 – Address: 0x03, Default: 0xF000

Register Name	Address	Bit	Name	Function	Default Value
config3	0x03	15:12	coarse_dac(3:0)	Scales the output current in 16 equal steps. $I_{FS} = \frac{V_{EXTIO}}{R_{BIAS}} \times 2 \times (\text{coarse_dac} + 1)$	1111
		11:8	Reserved	Reserved for factory use.	0000
		7:1	Reserved	Reserved for factory use.	0000000
		0	sif_txenable	When set, the internal value of TXENABLE is set to "1". To enable analog output data transmission, set <i>sif_txenable</i> to "1" or pull CMOS TXENA pin (N9) to high. To disable analog output, set <i>sif_txenable</i> to "0" and pull CMOS TXENA pin (N9) to low.	0

Register name: config4 – Address: 0x04, Default: No RESET Value (WRITE TO CLEAR)

Register Name	Address	Bit	Name	Function	Default Value
config4	0x04	15:0	iotest_results(15:0)	Bits in iotest_results with logic value of “1” tell which bit in either DAB[15:0] bus or DCD[15:0] bus failed during the pattern checker test. <i>iotest_results</i> (15:8) correspond to the data bits on both DAB[15:8] and DCD[15:8]. <i>iotest_results</i> (7:0) correspond to the data bits on both DAB[7:0] and DCD[7:0].	No RESET Value

Register name: config5 – Address: 0x05, Default: 0x0000 (WRITE TO CLEAR)

Register Name	Address	Bit	Name	Function	Default Value
config5	0x05	15	alarm_from_zerochk	Alarm indicating the FIFO write pointer has an all zeros pattern in it. Since this pointer is a shift register, all zeros will cause the input point to be stuck until the next sync. This alarm allows checking for this condition. This alarm indicates that another sync is necessary to restart the FIFO pointer	0
		14	Reserved	Reserved for factory use.	0
		13:11	alarms_from_fifo(2:0)	Alarm indicating FIFO pointer collisions and nearness: 000: All fine 001: Pointers are 2 away 01x: Pointers are 1 away 1xx: FIFO pointer collision If the FIFO pointer collision alarm is set when <i>collisiongone_ena</i> is enabled, the FIFO must be re-synchronized and the bits must be cleared to resume normal operation.	000
		10	alarm_dacclk_gone	Alarm indicating the DACCLK has been stopped. If the bit is set when <i>dacclkgone_ena</i> is enabled, the DACCLK must resume and the bit must be cleared to resume normal operation.	0
		9	alarm_dataclk_gone	Alarm indicating the DATACLK has been stopped. If the bit is set when <i>dataclkgone_ena</i> is enabled, the DATACLK must resume and the bit must be cleared to resume normal operation.	0
		8	clock_gone	Alarm indicating either <i>alarm_dacclk_gone</i> or <i>alarm_dataclk_gone</i> are asserted. It controls the output. When high it will output “0x8000” for each output connected to the DAC. If the bit is set when <i>dacclkgone_ena</i> and/or <i>dataclkgone_ena</i> are enabled, the DACCLK and/or the DATACLK must resume and the bit must be cleared to resume normal operation.	0
		7	alarm_from_iotest	Alarm indicating the input data pattern does not match the pattern in the iotest_pattern registers.	0
		6	Reserved	Reserved for factory use.	0
		5	alarm_from_pll	Alarm indicating the PLL has lost lock.	0
		4	alarm_Aparity	In dual parity mode, alarm indicating a parity error on the A word. In single parity mode, alarm on the 32-bit data captured on the rising edge of DATACLKP/N.	0
		3	alarm_Bparity	In dual parity mode, alarm indicating a parity error on the B word. In single parity mode, alarm on the 32-bit data captured on the falling edge of DATACLKP/N.	0
		2	alarm_Cparity	In dual parity mode, alarm indicating a parity error on the C word.	0
		1	alarm_Dparity	In dual parity mode, alarm indicating a parity error on the D word.	0
		0	Reserved	Reserved for factory use.	0

Register name: config6 – Address: 0x06, Default: No RESET Value (READ ONLY)

Register Name	Address	Bit	Name	Function	Default Value
config6	0x06	15:8	tempdata(7:0)	This is the output from the chip temperature sensor. The value of this register in two's complement format represents the temperature in degrees Celsius. This register must be read with a minimum SCLK period of 1µs.	No RESET Value
		7:2	Reserved	Reserved for factory use.	000000
		1	Reserved	Reserved for factory use.	0
		0	Reserved	Reserved for factory use.	0

Register name: config7 – Address: 0x07, Default: 0xFFFF

Register Name	Address	Bit	Name	Function	Default Value																																		
config7	0x07	15:0	alarms_mask(15:0)	<p>These bits control the masking of the alarms. (0=not masked, 1= masked)</p> <table border="0"> <thead> <tr> <th>alarm_mask</th> <th>Alarm that is Masked</th> </tr> </thead> <tbody> <tr><td>15</td><td>alarm_from_zerockh</td></tr> <tr><td>14</td><td>not used</td></tr> <tr><td>13</td><td>alarm_fifo_collision</td></tr> <tr><td>12</td><td>alarm_fifo_1away</td></tr> <tr><td>11</td><td>alarm_fifo_2away</td></tr> <tr><td>10</td><td>alarm_dacclk_gone</td></tr> <tr><td>9</td><td>alarm_dataclk_gone</td></tr> <tr><td>8</td><td>alarm_output_gone</td></tr> <tr><td>7</td><td>alarm_from_iotest</td></tr> <tr><td>6</td><td>not used</td></tr> <tr><td>5</td><td>alarm_from_pll</td></tr> <tr><td>4</td><td>alarm_rparity</td></tr> <tr><td>3</td><td>alarm_lparity</td></tr> <tr><td>2</td><td>alarm_frame_parity</td></tr> <tr><td>1</td><td>not used</td></tr> <tr><td>0</td><td>not used</td></tr> </tbody> </table>	alarm_mask	Alarm that is Masked	15	alarm_from_zerockh	14	not used	13	alarm_fifo_collision	12	alarm_fifo_1away	11	alarm_fifo_2away	10	alarm_dacclk_gone	9	alarm_dataclk_gone	8	alarm_output_gone	7	alarm_from_iotest	6	not used	5	alarm_from_pll	4	alarm_rparity	3	alarm_lparity	2	alarm_frame_parity	1	not used	0	not used	0xFFFF
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3	alarm_lparity																																						
2	alarm_frame_parity																																						
1	not used																																						
0	not used																																						

Register name: config8 – Address: 0x08, Default: 0x0000 (CAUSES AUTO-SYNC)

Register Name	Address	Bit	Name	Function	Default Value
config8	0x08	15	Reserved	Reserved for factory use.	0
		14	Reserved	Reserved for factory use.	0
		13	Reserved	Reserved for factory use.	0
		12:0	qmc_offset(12:0)	DACI offset correction. The offset is measured in DAC LSBs. If enabled in config30 writing to this register causes an auto-sync to be generated. This loads the values of the QMC offset registers (config8-config9) into the offset block at the same time. When updating the offset values config8 should be written last. Programming config9 will not affect the offset setting.	All zeros

Register name: config9 – Address: 0x09, Default: 0x8000

Register Name	Address	Bit	Name	Function	Default Value
config9	0x09	15:13	fifo_offset(2:0)	When the sync to the FIFO occurs, this is the value loaded into the FIFO read pointer. With this value the initial difference between write and read pointers can be controlled. This may be helpful in syncing multiple chips or controlling the delay through the device.	100
		12:0	qmc_offsetQ(12:0)	DACQ offset correction. The offset is measured in DAC LSBs.	All zeros

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Register name: config10 – Address: 0x0A, Default: 0x0000 (CAUSES AUTO-SYNC)

Register Name	Address	Bit	Name	Function	Default Value
config10	0x0A	15	Reserved	Reserved for factory use.	0
		14	Reserved	Reserved for factory use.	0
		13	Reserved	Reserved for factory use.	0
		12:0		DACC offset correction. The offset is measured in DAC LSBs. If enabled in config30 writing to this register causes an auto-sync to be generated. This loads the values of the CD-channel QMC offset registers (config10-config11) into the offset block at the same time. When updating the offset values for the CD-channel config10 should be written last. Programming config11 will not affect the offset setting.	All zeros

Register name: config11 – Address: 0x0B, Default: 0x0000

Register Name	Address	Bit	Name	Function	Default Value
config11	0x0b	15	Reserved	Reserved for factory use.	0
		14	Reserved	Reserved for factory use.	0
		13	Reserved	Reserved for factory use.	0
		12:0	qmc_offsetD(12:0)	DACD offset correction. The offset is measured in DAC LSBs.	All zeros

Register name: config12 – Address: 0x0C, Default: 0x0400

Register Name	Address	Bit	Name	Function	Default Value
config12	0x0C	15	Reserved	Reserved for factory use.	0
		14	Reserved	Reserved for factory use.	0
		13	Reserved	Reserved for factory use.	0
		12	Reserved	Reserved for factory use.	0
		11	Reserved	Reserved for factory use.	0
		10:0	qmc_gainI(10:0)	QMC gain for DACI. The full 11-bit qmc_gainA(10:0) word is formatted as UNSIGNED with a range of 0 to 1.9990. The implied decimal point for the multiplication is between bit 9 and bit 10.	10000000 000

Register name: config13 – Address: 0x0D, Default: 0x0400

Register Name	Address	Bit	Name	Function	Default Value
config13	0x0D	15	cmix_mode(3:0)	Sets the mixing function of the coarse mixer. Bit 0: -Fs/4 mixer Bit 1: Fs/2 mixer Bit 2: Fs/4 mixer Bit 3: Fs/8 mixer The various mixers can be combined together to obtain a $\pm n \times Fs/8$ total mixing factor.	0000
		11	Reserved	Reserved for factory use.	0
		10:0	qmc_gainB(10:0)	QMC gain for DACB. The full 11-bit qmc_gainB(10:0) word is formatted as UNSIGNED with a range of 0 to 1.9990. The implied decimal point for the multiplication is between bit 9 and bit 10.	10000000 000

Register name: config14 – Address: 0x0E, Default: 0x0400

Register Name	Address	Bit	Name	Function	Default Value
config14	0x0E	15	Reserved	Reserved for factory use.	0
		14	Reserved	Reserved for factory use.	0
		13	Reserved	Reserved for factory use.	0
		12	Reserved	Reserved for factory use.	0
		11	Reserved	Reserved for factory use.	0
		10:0	gmc_gainC(10:0)	QMC gain for DACC. The full 11-bit qmc_gainC(10:0) word is formatted as UNSIGNED with a range of 0 to 1.9990. The implied decimal point for the multiplication is between bit 9 and bit 10.	10000000 000

Register name: config15 – Address: 0x0F, Default: 0x0400

Register Name	Address	Bit	Name	Function	Default Value
config15	0x0F	15:14	output_delay(1:0)	Delays the DAC outputs from 0 to 3 DAC clock cycles.	00
		13:12	Reserved	Reserved for factory use.	00
		11	Reserved	Reserved for factory use.	0
		10:0	gmc_gainD(10:0)	QMC gain for DACD. The full 11-bit gmc_gainD(10:0) word is formatted as UNSIGNED with a range of 0 to 1.9990. The implied decimal point for the multiplication is between bit 9 and bit 10.	10000000 000

Register name: config16 – Address: 0x10, Default: 0x0000 (CAUSES AUTO-SYNC)

Register Name	Address	Bit	Name	Function	Default Value
config16	0x10	15	Reserved	Reserved for factory use.	0
		14	Reserved	Reserved for factory use.	0
		13	Reserved	Reserved for factory use.	0
		12	Reserved	Reserved for factory use.	0
		11:0	qmc_phaseAB(11:0)	QMC correction phase for the AB data path. The 12-bit qmc_phaseAB(11:0) word is formatted as two's complement and scaled to occupy a range of -0.5 to 0.49975 and a default phase correction of 0.00. To accomplish QMC phase correction, this value is multiplied by the current B sample, then summed into the A sample. If enabled in config30 writing to this register causes an auto-sync to be generated. This loads the values of the QMC offset registers (config12, config13, and config16) into the QMC block at the same time. When updating the QMC values config16 should be written last. Programming config12 and config13 will not affect the QMC settings.	All zeros

Register name: config17 – Address: 0x11, Default: 0x0000 (CAUSES AUTO-SYNC)

Register Name	Address	Bit	Name	Function	Default Value
config17	0x11	15	Reserved	Reserved for factory use.	0
		14	Reserved	Reserved for factory use.	0
		13	Reserved	Reserved for factory use.	0
		12	Reserved	Reserved for factory use.	0
		11:0	qmc_phaseCD(11:0)	QMC correction phase for the CD data path. The 12-bit qmc_gainCD(11:0) word is formatted as two's complement and scaled to occupy a range of -0.5 to 0.49975 and a default phase correction of 0.00. To accomplish QMC phase correction, this value is multiplied by the current D sample, then summed into the C sample. If enabled in config30 writing to this register causes an auto-sync to be generated. This loads the values of the CD-channel QMC block registers (config14, config15 and config17) into the QMC block at the same time. When updating the QMC values for the CD-channel config17 should be written last. Programming config14 and config15 will not affect the QMC settings.	All zeros

Register name: config18 – Address: 0x12, Default: 0x0000 (CAUSES AUTO-SYNC)

Register Name	Address	Bit	Name	Function	Default Value
config18	0x12	15:0	phase_offsetAB(15:0)	Phase offset added to the CD data path NCO accumulator before the generation of the SIN and COS values. The phase offset is added to the upper 16 bits of the NCO accumulator results and these 16 bits are used in the sin/cos lookup tables. If enabled in config31 writing to this register causes an auto-sync to be generated. This loads the values of the fine mixer block registers (config18, config20, and config21) at the same time. When updating the mixer values the config18 should be written last. Programming config20 and config21 will not affect the mixer settings.	0x0000

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Register name: config19 – Address: 0x13, Default: 0x0000 (CAUSES AUTO-SYNC)

Register Name	Address	Bit	Name	Function	Default Value
config19	0x13	15:0	phase_offsetCD(15:0)	Phase offset added to the CD data path NCO accumulator before the generation of the SIN and COS values. The phase offset is added to the upper 16 bits of the NCO accumulator results and these 16 bits are used in the sin/cos lookup tables. If enabled in config31 writing to this register causes an auto-sync to be generated. This loads the values of the CD-channel fine mixer block registers (config19, config22, and config23) at the same time. When updating the mixer values for the CD-channel config19 should be written last. Programming config22 and config23 will not affect the mixer settings.	0x0000

Register name: config20 – Address: 0x14, Default: 0x0000

Register Name	Address	Bit	Name	Function	Default Value
config20	0x14	15:0	phase_addAB(15:0)	The phase_addAB(15:0) value is used to determine the NCO frequency. The two's complement formatted value can be positive or negative. Each LSB represents $F_s/(2^{32})$ frequency step.	0x0000

Register name: config21 – Address: 0x15, Default: 0x0000

Register Name	Address	Bit	Name	Function	Default Value
config21	0x15	15:0	phase_addAB(31:16)	See config20 above.	0x0000

Register name: config22 – Address: 0x16, Default: 0x0000

Register Name	Address	Bit	Name	Function	Default Value
config22	0x16	15:0	phase_addCD(15:0)	The phase_addCD(15:0) value is used to determine the NCO frequency. The two's complement formatted value can be positive or negative. Each LSB represents $F_s/(2^{32})$ frequency step.	0x0000

Register name: config23 – Address: 0x17, Default: 0x0000

Register Name	Address	Bit	Name	Function	Default Value
config23	0x17	15:0	phase_addCD(31:16)	See config22 above.	0x0000

Register name: config24 – Address: 0x18, Default: NA

Register Name	Address	Bit	Name	Function	Default Value
config24	0x18	15:13	Reserved	Reserved for factory use.	001
		12	pll_reset	When set, the PLL loop filter (LPF) is pulled down to 0V. Toggle from '1' to '0' to restart the PLL if an over-speed lock-up occurs. Over-speed can happen when the process is fast, the supplies are higher than nominal, etc. resulting in the feedback dividers missing a clock.	0
		11	pll_ndivsync_ena	When set, the LVDS SYNC input is used to sync the PLL N dividers.	1
		10	pll_ena	When set, the PLL is enabled. When cleared, the PLL is bypassed.	0
		9:8	Reserved	Reserved for factory use.	00
		7:6	pll_cp(1:0)	PLL pump charge select 00: No charge pump 01: Single pump charge 10: Not used 11: Dual pump charge	00
		5:3	pll_p(2:0)	PLL pre-scaler dividing module control. 010: 2 011: 3 100: 4 101: 5 110: 6 111: 7 000: 8	001

Register Name	Address	Bit	Name	Function	Default Value
		2:0	pll_lfvolt(2:0)	PLL loop filter voltage. Read only bits.	NA

Register name: config25 – Address: 0x19, Default: 0x0440

Register Name	Address	Bit	Name	Function	Default Value
config25	0x19	15:8	pll_m(7:0)	M portion of the M/N divider of the PLL. (0001=1, 0010=2, ..., 0000=256)	0x04
		7:4	pll_n(3:0)	N portion of the M/N divider of the PLL. (0000=1, 1111=16)	0100
		3:2	pll_vcoitune(1:0)	PLL VCO bias tuning bits.	00
		1:0	Reserved	Reserved for factory use.	00

Register name: config26 – Address: 0x1A, Default: 0x0020

Register Name	Address	Bit	Name	Function	Default Value
config26	0x1A	15:10	pll_vco(6:0)	VCO frequency coarse tuning bits.	000000
		9	Reserved	Reserved for factory use.	0
		8	Reserved	Reserved for factory use.	0
		7	bias_sleep	When set, the bias amplifier is put into sleep mode.	0
		6	tsense_sleep	Turns off the temperature sensor when asserted.	0
		5	pll_sleep	When set, the PLL is put into sleep mode.	1
		4	clkrecv_sleep	When asserted the clock input receiver gets put into sleep mode. This affects the OSTR receiver as well.	0
		3	sleepA	When set, the DACA is put into sleep mode.	0
		2	sleepB	When set, the DACB is put into sleep mode.	0
		1	sleepC	When set, the DACC is put into sleep mode.	0
0	sleepD	When set, the DACD is put into sleep mode.	0		

Register name: config27 – Address: 0x1B, Default: 0x0000

Register Name	Address	Bit	Name	Function	Default Value
config27	0x1B	15	extref_ena	Allows the device to use an external reference or the internal reference. 0: Internal reference 1: External reference	0
		14	Reserved	Reserved for factory use.	0
		13	Reserved	Reserved for factory use.	0
		12	Reserved	Reserved for factory use.	0
		11	Reserved	Reserved for factory use. Note: Default value is '0'. Must be set to '1' for proper operation	0
		10	Reserved	Reserved for factory use.	0
		9	Reserved	Reserved for factory use.	0
		8	Reserved	Reserved for factory use.	0
		7	Reserved	Reserved for factory use.	0
		6	Reserved	Reserved for factory use.	0
		5:0	Reserved	Reserved for factory use.	000000

Register name: config28 – Address: 0x1C, Default: 0x0000

Register Name	Address	Bit	Name	Function	Default Value
config28	0x1C	15:8	Reserved	Reserved for factory use.	0x00
		7:0	Reserved	Reserved for factory use.	0x00

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Register name: config29 – Address: 0x1D, Default: 0x0000

Register Name	Address	Bit	Name	Function	Default Value
config29	0x1D	15:8	Reserved	Reserved for factory use.	0x00
		7:0	Reserved	Reserved for factory use.	0x00

Register name: config30 – Address: 0x1E, Default: 0x1111

Register Name	Address	Bit	Name	Function	Default Value
config30	0x1E	15:12	syncsel_qmoffsetAB(4:0)	Selects the syncing source(s) of the AB data path double buffered QMC offset registers. A '1' in the bit enables the signal as a sync source. More than one sync source is permitted. Bit 0: Auto-sync from register write Bit 1: OSTR Bit 2: SYNC from FIFO output Bit 3: sif_sync (via <i>config31</i>)	0001
		11:8	syncsel_qmoffsetCD(4:0)	Selects the syncing source(s) of the CD data path double buffered QMC offset registers. A '1' in the bit enables the signal as a sync source. More than one sync source is permitted. Bit 0: Auto-sync from register write Bit 1: OSTR Bit 2: SYNC from FIFO output Bit 3: sif_sync (via <i>config31</i>)	0001
		7:4	syncsel_qmcorrAB(4:0)	Selects the syncing source(s) of the AB data path double buffered QMC offset registers. A '1' in the bit enables the signal as a sync source. More than one sync source is permitted. Bit 0: Auto-sync from register write Bit 1: OSTR Bit 2: SYNC from FIFO output Bit 3: sif_sync (via <i>config31</i>)	0001
		3:0	syncsel_qmcorrCD(4:0)	Selects the syncing source(s) of the CD data path double buffered QMC offset registers. A '1' in the bit enables the signal as a sync source. More than one sync source is permitted. Bit 0: Auto-sync from register write Bit 1: OSTR Bit 2: SYNC from FIFO output Bit 3: sif_sync (via <i>config31</i>)	0001

Register name: config31 – Address: 0x1F, Default: 0x1140

Register Name	Address	Bit	Name	Function	Default Value
config31	0x1F	15:12	syncsel_mixerAB(4:0)	Selects the syncing source(s) of the AB data path double buffered mixer registers. A '1' in the bit enables the signal as a sync source. More than one sync source is permitted. Bit 0: Auto-sync from register write Bit 1: OSTR Bit 2: SYNC from FIFO output Bit 3: sif_sync (via <i>config31</i>)	0001
		11:8	syncsel_mixerCD(4:0)	Selects the syncing source(s) of the CD data path double buffered mixer registers. A '1' in the bit enables the signal as a sync source. More than one sync source is permitted. Bit 0: Auto-sync from register write Bit 1: OSTR Bit 2: SYNC from FIFO output Bit 3: sif_sync (via <i>config31</i>)	0001
		7:4	syncsel_nco(4:0)	Selects the syncing source(s) of the two NCO accumulators. A '1' in the bit enables the signal as a sync source. More than one sync source is permitted. Bit 0: ISTR from FIFO output Bit 1: OSTR Bit 2: SYNC from FIFO output Bit 3: sif_sync (via <i>config31</i>)	0100

Register Name	Address	Bit	Name	Function	Default Value
		3:2	syncsel_dataformatter	Selects the syncing source of the data formatter. Unlike the other syncs only one sync source is allowed. 00: ISTR from LVDS receivers 01: SYNC from LVDS receivers 10: No sync 11: No sync	00
		1	sif_sync	SIF created sync signal. Set to '1' to cause a sync and then clear to '0' to remove it.	0
		0	Reserved	Reserved for factory use.	0

Register name: config32 – Address: 0x20, Default: 0x2400

Register Name	Address	Bit	Name	Function	Default Value				
config32	0x20	15:12	syncsel_fifo(4:0)	Selects the syncing source(s) of the FIFO input side. A '1' in the bit enables the signal as a sync source. More than one sync source is permitted. Bit 0: SYNC from the data formatter block Bit 1: ISTR from the data formatter block Bit 2: Always zero Bit 3: sif_sync (via config31) – not recommended	0010				
		11:8	syncsel_fifoout(4:0)	Selects the syncing source(s) of the FIFO output side. A '1' in the bit enables the signal as a sync source. More than one sync source is permitted. Bit 0: SYNC from the data formatter block – Single Sync Source mode Bit 1: ISTR from the data formatter block –Single Sync Source mode Bit 2: OSTR – Dual Sync Source Mode Bit 3: sif_sync (via config31) – not recommended	0100				
		7:1	Reserved	Reserved for factory use.	0000				
		0	clkdiv_sync_sel	Selects the signal source for clock divider synchronization. <table border="1" style="width: 100%; border-collapse: collapse;"> <thead> <tr> <th style="text-align: left;">multi_sync_sel</th> <th style="text-align: left;">Sync Source</th> </tr> </thead> <tbody> <tr> <td style="text-align: center;">0</td> <td>OSTR</td> </tr> <tr> <td style="text-align: center;">1</td> <td>ISTR or SYNC, based on syncsel_fifo(4:0) source selection (config32, bit<15:12>)</td> </tr> </tbody> </table>	multi_sync_sel	Sync Source	0	OSTR	1
multi_sync_sel	Sync Source								
0	OSTR								
1	ISTR or SYNC, based on syncsel_fifo(4:0) source selection (config32, bit<15:12>)								

Register name: config33 – Address: 0x21, Default: 0x0000

Register Name	Address	Bit	Name	Function	Default Value
config33	0x21	15:0	Reserved	Reserved for factory use.	0x0000

Register name: config34 – Address: 0x22, Default: 0x1B1B

Register Name	Address	Bit	Name	Function	Default Value
config34	0x22	15:14	pathA_in_sel(1:0)	Selects the word used for the A channel path.	00
		13:12	pathB_in_sel(1:0)	Selects the word used for the B channel path.	01
		11:10	pathC_in_sel(1:0)	Selects the word used for the C channel path.	10
		9:8	pathD_in_sel(1:0)	Selects the word used for the D channel path.	11
		7:6	DACA_out_sel(1:0)	Selects the word used for the DACA output.	00
		5:4	DACB_out_sel(1:0)	Selects the word used for the DACB output.	01
		3:2	DACC_out_sel(1:0)	Selects the word used for the DACC output.	10
		1:0	DACD_out_sel(1:0)	Selects the word used for the DACD output.	11

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Register name: config35 – Address: 0x23, Default: 0xFFFF

Register Name	Address	Bit	Name	Function	Default Value	
config35	0x23	15:0	sleep_cntl(15:0)	Controls the routing of the CMOS SLEEP signal (pin B40) to different blocks. . When a bit in this register is set, the SLEEP signal will be sent to the corresponding block. The block will only be disabled when the SLEEP is logic HIGH and the correspond bit is set to "1"	0xFFFF	
				These bits do not override SIF bits in config26 that control the same sleep function.		
				sleep_cntl(bit)		Function
				15		DACA sleep
				14		DACB sleep
				13		DACC sleep
				12		DACD sleep
				11		Clock divider sleep
				10		PLL sleep
				9		LVDS data sleep
				8		LVDS control sleep
				7		Temp sensor sleep
				6		reserved
5	Bias amplifier sleep					
All others	not used					

Register name: config36 – Address: 0x24, Default: 0x0000

Register Name	Address	Bit	Name	Function	Default Value
config36	0x24	15:13	datadly(2:0)	Controls the delay of the data inputs through the LVDS receivers. Each LSB adds approximately 40 ps 0: Minimum	000
		12:10	clkdly(2:0)	Controls the delay of the data clock through the LVDS receivers. Each LSB adds approximately 40 ps 0: Minimum	000
		9:0	Reserved	Reserved for factory use.	0x0000

Register name: config37 – Address: 0x25, Default: 0x7A7A

Register Name	Address	Bit	Name	Function	Default Value
config37	0x25	15:0	iotest_pattern0	Dataword0 in the IO test pattern. It is used with the seven other words to test the input data. At the start of the IO test pattern, this word should be aligned with rising edge of ISTR or SYNC signal to indicate sample 0.	0x7A7A

Register name: config38 – Address: 0x26, Default: 0xB6B6

Register Name	Address	Bit	Name	Function	Default Value
config38	0x26	15:0	iotest_pattern1	Dataword1 in the IO test pattern. It is used with the seven other words to test the input data.	0xVB6B6

Register name: config39 – Address: 0x27, Default: 0xEAEA

Register Name	Address	Bit	Name	Function	Default Value
config39	0x27	15:0	iotest_pattern2	Dataword2 in the IO test pattern. It is used with the seven other words to test the input data.	0xEAEA

Register name: config40 – Address: 0x28, Default: 0x4545

Register Name	Address	Bit	Name	Function	Default Value
config40	0x28	15:0	iotest_pattern3	Dataword3 in the IO test pattern. It is used with the seven other words to test the input data.	0x4545

Register name: config41 – Address: 0x29, Default: 0x1A1A

Register Name	Address	Bit	Name	Function	Default Value
config41	0x29	15:0	iotest_pattern2	Dataword4 in the IO test pattern. It is used with the seven other words to test the input data.	0x1A1A

Register name: config42 – Address: 0x2A, Default: 0x1616

Register Name	Address	Bit	Name	Function	Default Value
config42	0x2A	15:0	iotest_pattern5	Dataword5 in the IO test pattern. It is used with the seven other words to test the input data.	0x1616

Register name: config43 – Address: 0x2B, Default: 0xAAAA

Register Name	Address	Bit	Name	Function	Default Value
config43	0x2B	15:0	iotest_pattern6	Dataword6 in the IO test pattern. It is used with the seven other words to test the input data.	0xAAAA

Register name: config44 – Address: 0x2C, Default: 0xC6C6

Register Name	Address	Bit	Name	Function	Default Value
config44	0x2C	15:0	iotest_pattern7	Dataword7 in the IO test pattern. It is used with the seven other words to test the input data.	0xC6C6

Register name: config45 – Address: 0x2D, Default: 0x0004

Register Name	Address	Bit	Name	Function	Default Value
config45	0x2D	15	fifoalarm_resync	When set, the FIFO gets re-synced automatically when a collision alarm occurs.	0
		14	ostrtodig_sel	When set, the OSTR signal is passed directly to the digital block. This is the signal that is used to clock the dividers.	0
		13	ramp_ena	When set, a ramp signal is inserted in the input data at the FIFO input.	0
		12:1	Reserved	Reserved for factory use.	0x0004
		0	sifdac_ena	When set, the DAC output is set to the value in <i>sifdac(15:0)</i> in register <i>config48</i> .	0

Register name: config46 – Address: 0x2E, Default: 0x0000

Register Name	Address	Bit	Name	Function	Default Value
config46	0x2E	15:8	grp_delaya(7:0)	Sets the group delay function for DACA. The delay range is approximately 100ps.	0x00
		7:0	grp_delayB(7:0)	Sets the group delay function for DACB. The delay range is approximately 100ps.	0x00

Register name: config47 – Address: 0x2F, Default: 0x0000

Register Name	Address	Bit	Name	Function	Default Value
config47	0x2F	15:8	grp_delayC(7:0)	Sets the group delay function for DACC. The delay range is approximately 100ps.	0x00
		7:0	grp_delayD(7:0)	Sets the group delay function for DACD. The delay range is approximately 100ps.	0x00

Register name: config48 – Address: 0x30, Default: 0x0000

Register Name	Address	Bit	Name	Function	Default Value
config48	0x2F	15:0	sifdac(15:0)	Value sent to the DACs when <i>sifdac_ena</i> is asserted. DATACLK must be running to latch this value into the DACs. The format would be based on twos in register <i>config2</i> .	0x0000

Register name: version– Address: 0x7F, Default: 0x5409 (READ ONLY)

Register Name	Address	Bit	Name	Function	Default Value
version	0x7F	15:10	Reserved	Reserved for factory use.	010101
		9	Reserved	Reserved for factory use.	0
		8:7	Reserved	Reserved for factory use.	00
		6:5	Reserved	Reserved for factory use.	00
		4:3	deviceid(1:0)	Returns '01' for DAC34H84.	01
		2:0	versionid(2:0)	A hardwired register that contains the version of the chip.	001

DATA INTERFACE

The DAC34H84 has a 32-bit LVDS bus that accepts quad, 16-bit data in word-wide format. The quad-16-bit data can be input to the device using a dual-bus, 16-bit interface. The bus accepts LVDS transfer rates up to 1.25GSPS which corresponds to a maximum data rate of 625MSPS per data channel. The default LVDS bus input assignment is shown in [Table 3](#).

Table 3. LVDS Bus Input Assignment

Data Paths	Pins
A and B	DAB[15..0]
C and D	DCD[15..0]

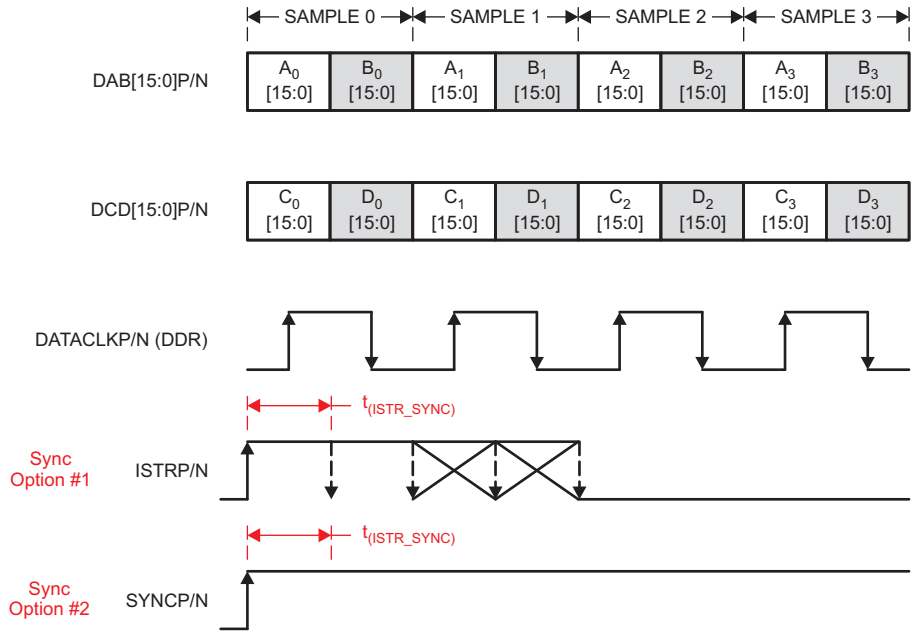
Data is sampled by the LVDS double data rate (DDR) clock DATACLK. Setup and hold requirements must be met for proper sampling. A and C data are captured on the rising edge of DATACLK. B and D data are captured on the falling edge of DATACLK.

For both input bus modes, a sync signal, either ISTR or SYNC, is required to sync the FIFO read and/or write pointers.

The sync signal, either ISTR or SYNC, can be either a pulse or a periodic signal where the sync period corresponds to multiples of 8 samples. ISTR or SYNC is sampled by a rising edge in DATACLK. The pulse-width $t_{(ISTR_SYNC)}$ needs to be at least equal to 1/2 of the DATACLK period.

DATA FORMAT

The 16-bit data for channels A and B is interleaved in the form $A_0[15:0], B_0[15:0], A_1[15:0], B_1[15:0], A_2[15:0]...$ into the DAB[15:0]P/N LVDS inputs. Similarly data for channels C and D is interleaved into the DCD[15:0]P/N LVDS inputs. Data into the DAC34H84 is formatted according to the diagram shown in [Figure 3](#) where index 0 is the data LSB and index 15 is the data MSB.



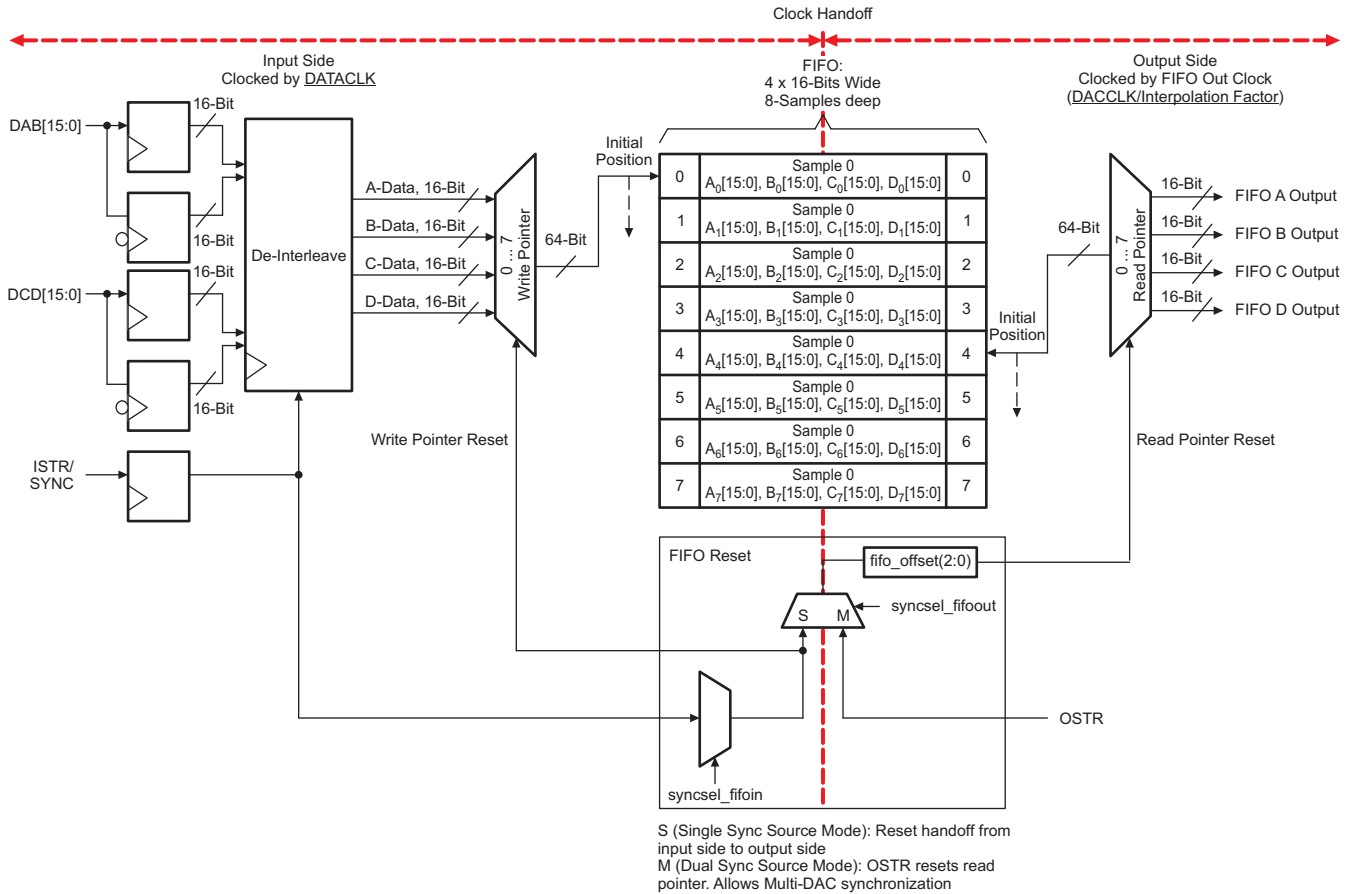
T0530-01

Figure 3. Data Transmission Format

INPUT FIFO

The DAC34H84 includes a 4-channel, 16-bits wide and 8-samples deep input FIFO which acts as an elastic buffer. The purpose of the FIFO is to absorb any timing variations between the input data and the internal DAC data rate clock such as the ones resulting from clock-to-data variations from the data source.

Figure 4 shows a simplified block diagram of the FIFO.



B0461-01

Figure 4. DAC34H84 FIFO Block Diagram

Data is written to the device 32-bits at a time on the rising and falling edges of DATACLK. In order to form a complete 64-bit wide sample (16-bit A-data, 16-bit B-data, 16-bit C-data, and 16-bit D-data) one DATACLK period is required. Each 64-bit wide sample is written into the FIFO at the address indicated by the write pointer. Similarly, data from the FIFO is read by the FIFO Out Clock 64-bits at a time from the address indicated by the read pointer. The FIFO Out Clock is generated internally from the DACCLK signal and its rate is equal to DACCLK/Interpolation. Each time a FIFO write or FIFO read is done the corresponding pointer moves to the next address.

The reset position for the FIFO read and write pointers is set by default to addresses 0 and 4 as shown in Figure 4. This offset gives optimal margin within the FIFO. The default read pointer location can be set to another value using *fifo_offset(2:0)* in register *config3* (address 4 by default). Under normal conditions data is written-to and read-from the FIFO at the same rate and consequently the write and read pointer gap remains constant. If the FIFO write and read rates are different, the corresponding pointers will be cycling at different speeds which could result in pointer collision. Under this condition the FIFO attempts to read and write data from the same address at the same time which will result in errors and thus must be avoided.

The write pointer sync source is selected by *syncsel_fifoin(4:0)* in register *config32*. In most applications either ISTR or SYNC are used to reset the write pointer. Unlike DATA, the sync signal is latched only on the rising edges of DATACLK. A rising edge on the sync signal source causes the pointer to return to its original position.

Similarly, the read pointer sync source is selected by *syncsel_fifoout(4:0)*. The write pointer sync source can be set to reset the read pointer as well. In this case, the read pointer is reset by an internal signal generated by recapturing the write pointer sync signal by the FIFO Out clock. This clock domain transfer (DATACLK to FIFO Out Clock) results in phase ambiguity of the reset signal. This limits the precise control of the output timing and makes full synchronization of multiple devices difficult.

To alleviate this, the device offers the alternative of resetting the FIFO read pointer independently of the write pointer by using the OSTR signal. The OSTR signal is sampled by DACCLK and must satisfy the timing requirements in the specifications table. In order to minimize the skew it is recommended to use the same clock distribution device such as Texas Instruments CDCE62005 to provide the DACCLK and OSTR signals to all the DAC34H84 devices in the system. Swapping the polarity of the DACCLK outputs with respect to the OSTR ones establishes proper phase relationship.

The FIFO pointers reset procedure can be done periodically or only once during initialization as the pointers automatically return to the initial position when the FIFO has been filled. To reset the FIFO periodically, it is necessary to have the ISTR, SYNC, and OSTR signals to repeat at multiples of 8 FIFO samples. To disable FIFO reset, set *syncsel_fifo*(4:0) and *syncsel_fifoout*(4:0) to "0000".

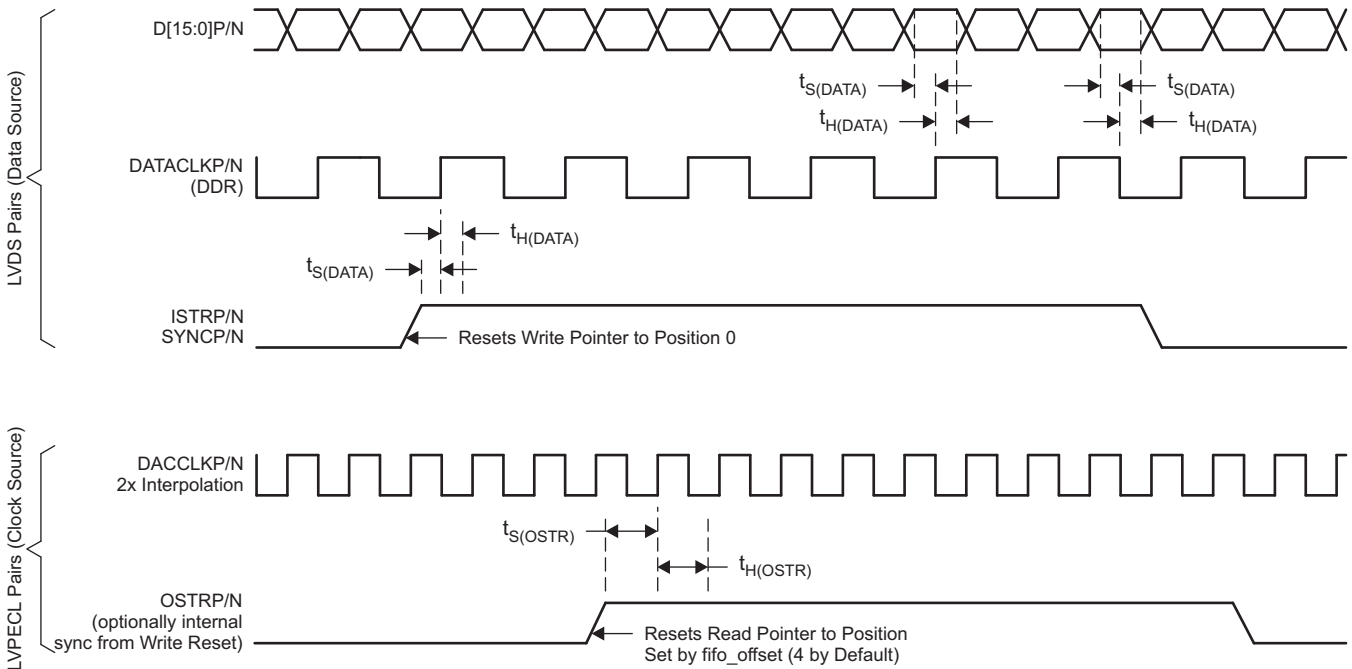
The frequency limitation for ISTR and SYNC signals are the following:

$$f_{sync} = f_{DATACLK} / (n \times 8) \text{ where } n = 1, 2, \dots$$

The frequency limitation for the OSTR signal is the following:

$$f_{OSTR} = f_{DAC} / (n \times \text{interpolation} \times 8) \text{ where } n = 1, 2, \dots$$

The frequencies above are at maximum when $n = 1$. This is when the ISTR, SYNC, or OSTR have a rising edge transition every 8 FIFO samples. The occurrence can be made less frequent by setting $n > 1$, for example, every $n \times 8$ FIFO samples.



T0531-01

Figure 5. FIFO Write and Read Descriptions

FIFO MODES OF OPERATION

The DAC34H84 input FIFO can be completely bypassed through registers *config1* and *config32*. The register configuration for each mode is described in [Table 4](#).

Register	Control Bits
config1	fifo_ena
config32	syncsel_fifoout(4:0)

Table 4. FIFO Operation Modes

FIFO Mode	config1 and config32 FIFO Bits				
	fifo_ena	syncsel_fifoout			
		Bit 3: sif_sync	Bit 2: OSTR	Bit 1: ISTR	Bit 0: SYNC
Dual Sync Source	1	0	1	0	0
Single Sync Source	1	0	0	1 or 0 Depends on the sync source	1 or 0 Depends on the sync source
Bypass	0	X	X	X	X

DUAL SYNC SOURCE MODE

This is the recommended mode of operation for those applications that require precise control of the output timing. In Dual Sync Source mode, the FIFO write and read pointers are reset independently. The FIFO write pointer is reset using the LVDS ISTR or SYNC signal, and the FIFO read pointer is reset using the LVPECL OSTR signal. This allows LVPECL OSTR signal to control the phase of the output for either a single chip or multiple chips. Multiple devices can be fully synchronized in this mode.

SINGLE SYNC SOURCE MODE

In Single Sync Source mode, the FIFO write and read pointers are reset from the same source, either LVDS ISTR or LVDS SYNC signal. This mode has a possibility of up to 2 DAC clocks offset between the multiple DAC outputs. Applications requiring exact output timing control will need Dual Sync Source mode instead of Single Sync Source Mode.

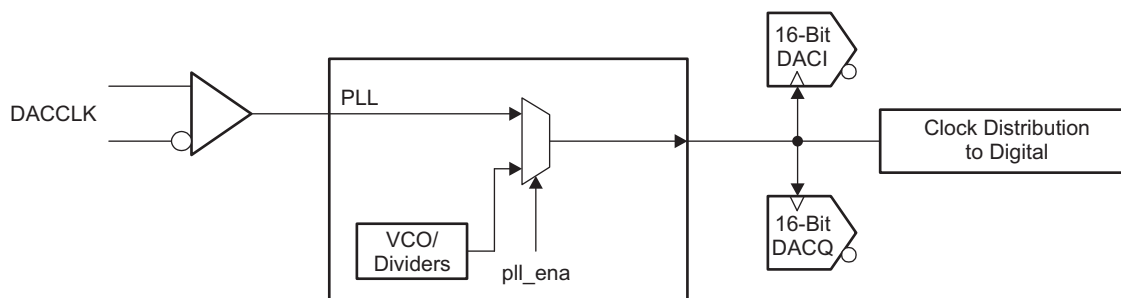
BYPASS MODE

In FIFO bypass mode, the FIFO block is not used. As a result the input data is handed off from the DATACLK to the DACCLK domain without any compensation. In this mode the relationship between DATACLK and DACCLK $t_{(align)}$ is critical and used as a synchronizing mechanism for the internal logic. Due to the $t_{(align)}$ constraint this mode is **not recommended**. In bypass mode the pointers have no effect on the data path or handoff.

CLOCKING MODES

The DAC34H84 has a dual clock setup in which a DAC clock signal is used to clock the DAC cores and internal digital logic and a separate DATA clock is used to clock the input LVDS receivers and FIFO input. The DAC34H84 DAC clock signal can be sourced directly or generated through an on-chip low-jitter phase-locked loop (PLL).

In those applications requiring extremely low noise it is recommended to bypass the PLL and source the DAC clock directly from a high-quality external clock to the DACCLK input. In most applications system clocking can be simplified by using the on-chip PLL to generate the DAC core clock while still satisfying performance requirements. In this case the DACCLK pins are used as the reference frequency input to the PLL.



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Figure 6. Top Level Clock Diagram

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PLL BYPASS MODE

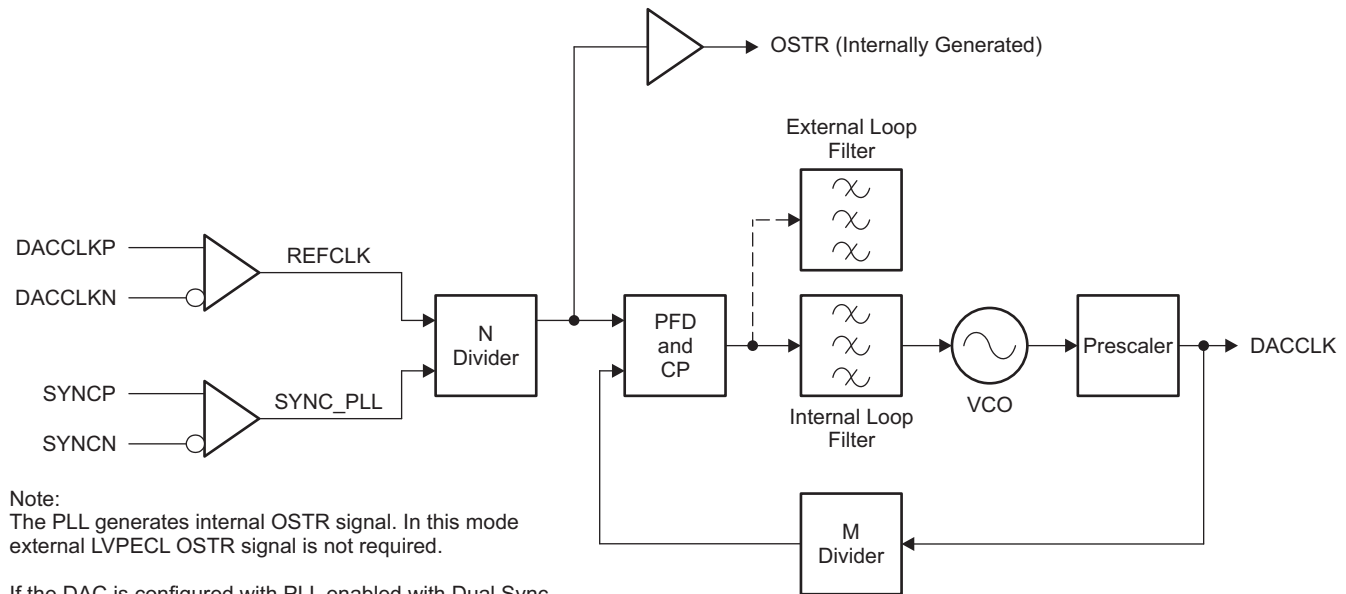
In PLL bypass mode a very high quality clock is sourced to the DACCLK inputs. This clock is used to directly clock the DAC34H84 DAC cores. This mode gives the device best performance and is recommended for extremely demanding applications.

The bypass mode is selected by setting the following:

1. *pll_ena* bit in register *config24* to “0” to bypass the PLL circuitry.
2. *pll_sleep* bit in register *config24* to “1” to put the PLL and VCO into sleep mode.

PLL MODE

In this mode the clock at the DACCLK input functions as a reference clock source to the on-chip PLL. The on-chip PLL will then multiply this reference clock to supply a higher frequency DAC cores clock. Figure 7 shows the block diagram of the PLL circuit.



Note:
The PLL generates internal OSTR signal. In this mode external LVPECL OSTR signal is not required.

If the DAC is configured with PLL enabled with Dual Sync Source mode, then the PFD frequency has to be the pre-defined OSTR frequency.

B0453-01

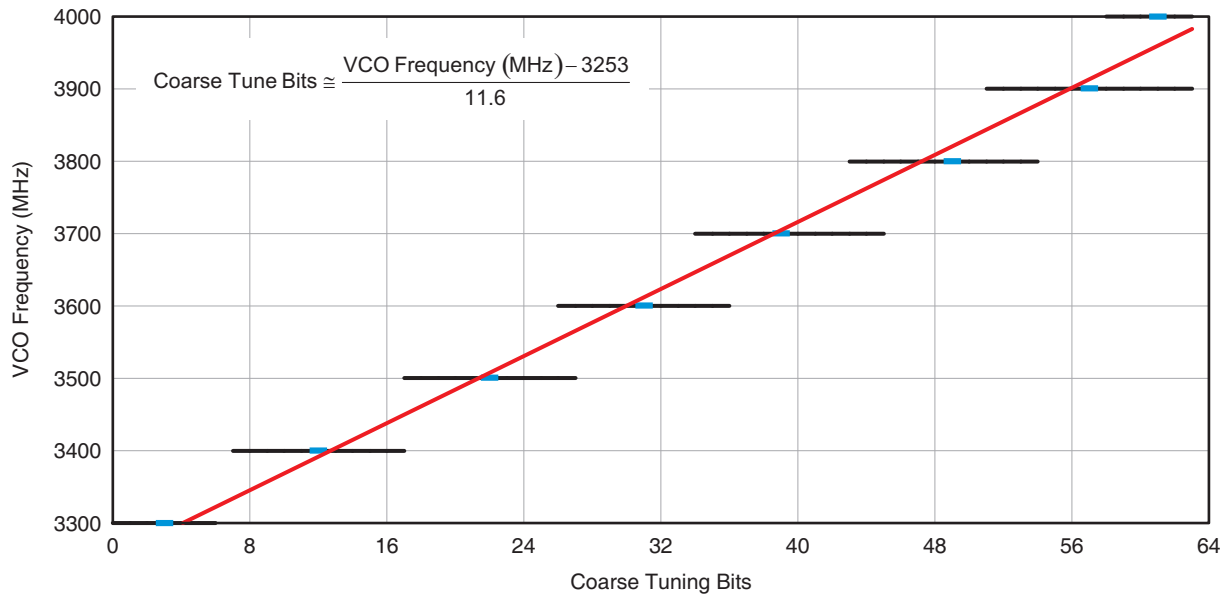
Figure 7. PLL Block Diagram

The DAC34H84 PLL mode is selected by setting the following:

1. *pll_ena* bit in register *config24* to “1” to route to the PLL clock path.
2. *pll_sleep* bit in register *config24* to “0” to enable the PLL and VCO.

The output frequency of the VCO is designed to be in the range from 3.3GHz to 4.0GHz. This VCO range is tuned to a target of 3.6864GHz but can be further adjusted by using the 6-bits *pll_vco* in register *config26*.

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Figure 8. Typical PLL/VCO Lock Range vs Coarse Tuning Bits

Common wireless infrastructure frequencies (614.4MHz, 737.28MHz, 1.2288GHz, etc.) are generated from this VCO frequency in conjunction with the pre-scaler setting *pll_p* in register *config24* as shown in Table 5.

Table 5. VCO Operation

VCO Frequency (MHz)	Pre-Scale Divider	Desired DACCLK (MHz)	pll_p(2:0)
3440.64	7	491.52	111
3686.4	6	614.4	110
3686.4	5	737.28	101
3686.4	3	1228.8	011

The M divider is used to determine the phase-frequency-detector (PFD) and charge-pump (CP) frequency.

Table 6. PFD and CP Operation

DACCLK Frequency (MHz)	M Divider	PDF Update Rate (MHz)	pll_m(7:0)
491.52	4	122.88	00000100
491.52	8	61.44	00001000
491.52	16	30.72	00010000
491.52	32	15.36	00100000

The N divider in the loop allows the PFD to operate at a lower frequency than the reference clock.

The overall divide ratio inside the loop is the product of the Pre-Scale and M dividers (P * M) and the following guidelines should be followed:

- The overall divide ratio range is from 24 to 480
- When the overall divide ratio is less than 120, the internal loop filter can assure a stable loop
- When the overall divide ration is greater than 120, either an external loop filter or a double charge pump setting are required to guarantee loop stability

The single and double charge pump current options are selected by setting *pll_cp* in register *config24* to “01” and “11” respectively. When using the double charge pump setting an external loop filter is not required.

If an external filter is required, the following filter should be connected to the LPF pin (A1):

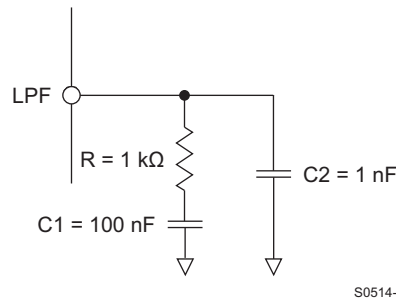


Figure 9. Recommended External Loop Filter

The PLL will generate an internal OSTR signal and does not require the external LVPECL OSTR signal. The OSTR signal is buffered from the N-divider output in the PLL block, and the frequency of the signal is the same as the PFD frequency. Therefore, using PLL with Dual Sync Source mode would require the PFD frequency to be the pre-defined OSTR frequency. This will allow the FIFO to be synced correctly by the internal OSTR.

MULTI-DEVICE SYNCHRONIZATION

In various applications, such as multi antenna systems where the various transmit channels information is correlated, it is required that multiple DAC devices are completely synchronized such that their outputs are phase aligned. The DAC34H84 architecture supports this mode of operation.

MULTI-DEVICE SYNCHRONIZATION: PLL BYPASSED WITH DUAL SYNC SOURCE MODE

For single- or multi-device synchronization it is important that delay differences in the data are absorbed by the device so that latency through the device remains the same. Furthermore, to ensure that the outputs from each DAC are phase aligned it is necessary that data is read from the FIFO of each device simultaneously. In the DAC34H84 this is accomplished by operating the multiple devices in Dual Sync Source mode. In this mode the additional OSTR signal is required by each DAC34H84 to be synchronized.

Data into the device is input as LVDS signals from one or multiple baseband ASICs or FPGAs. Data into the multiple DAC devices can experience different delays due to variations in the digital source output paths or board level wiring. These different delays can be effectively absorbed by the DAC34H84 FIFO so that all outputs are phase aligned correctly.

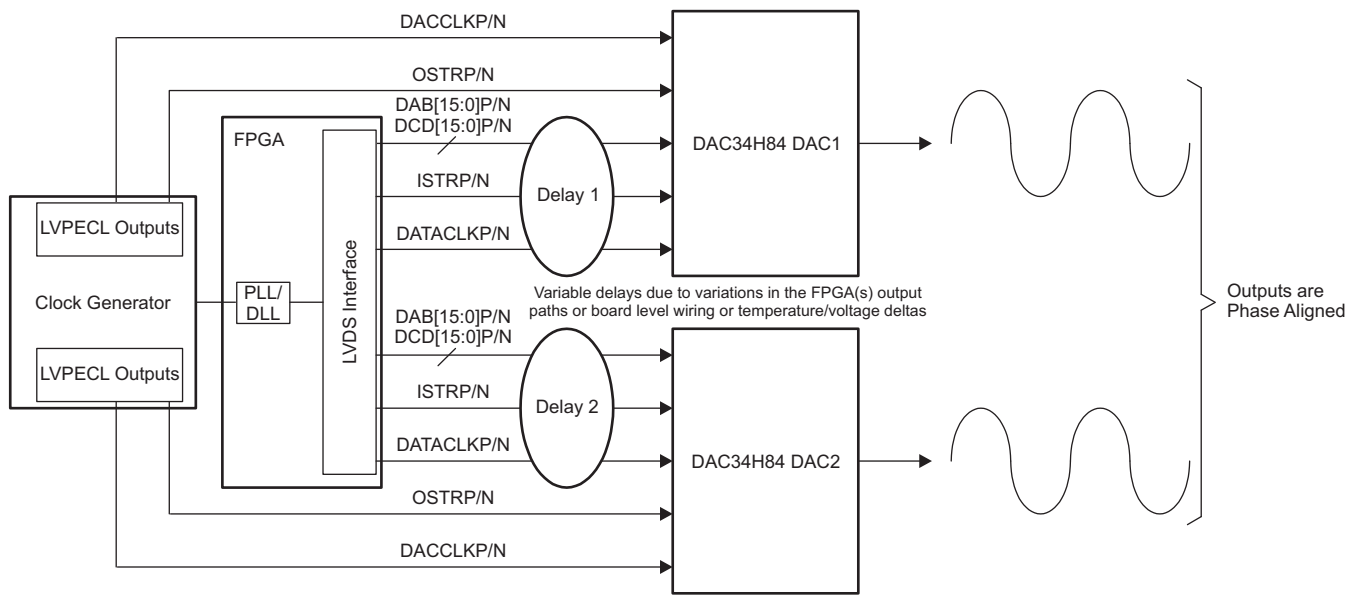
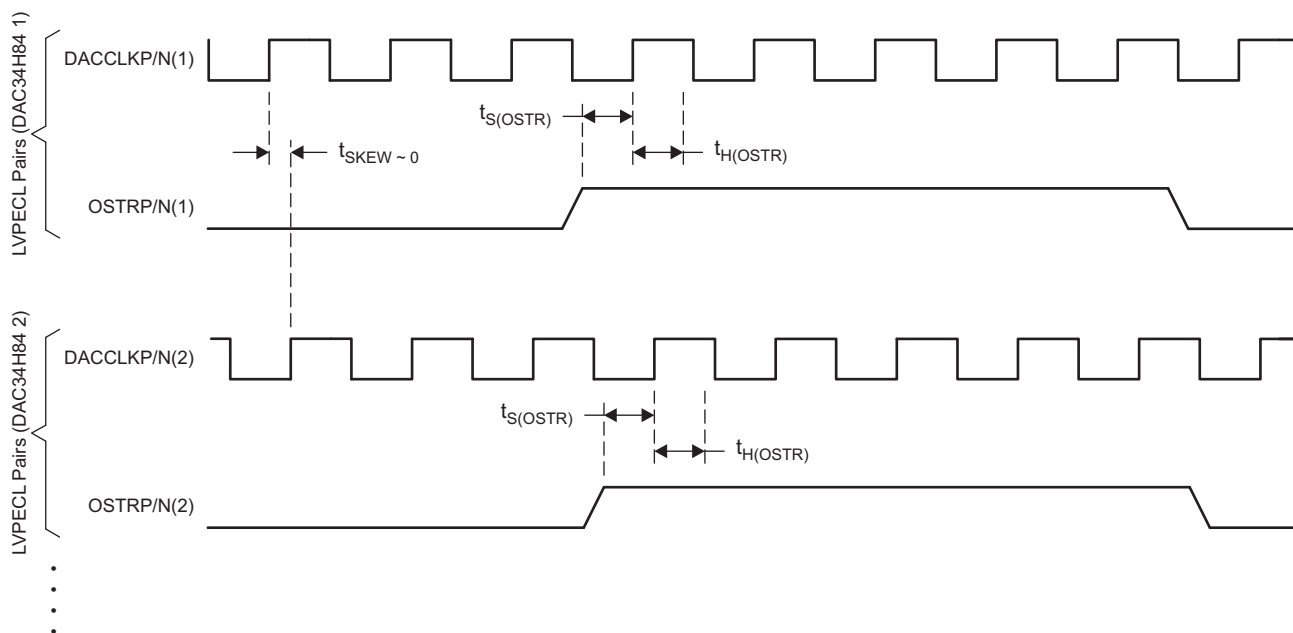


Figure 10. Synchronization System in Dual Sync Source Mode with PLL Bypassed

PRODUCT PREVIEW

For correct operation both OSTR and DACCLK must be generated from the same clock domain. The OSTR signal is sampled by DACCLK and must satisfy the timing requirements in the specifications table. If the clock generator does not have the ability to delay the DACCLK to meet the OSTR timing requirement, the polarity of the DACCLK outputs can be swapped with respect to the OSTR ones to create 180 degree phase delay of the DACCLK. This may help establish proper setup and hold time requirement of the OSTR signal.

Careful board layout planning must be done to ensure that the DACCLK and OSTR signals are distributed from device to device with the lowest skew possible as this will affect the synchronization process. In order to minimize the skew across devices it is recommended to use the same clock distribution device to provide the DACCLK and OSTR signals to all the DAC devices in the system.



T0526-02

Figure 11. Timing Diagram for LVPECL Synchronization Signals

The following steps are required to ensure the devices are fully synchronized. The procedure assumes all the DAC34H84 devices have a DACCLK and OSTR signal and must be carried out on each device.

1. Start-up the device as described in the power-up sequence. Set the DAC34H84 in Dual Sync Source mode and select OSTR as the clock divider sync source (*clkdiv_sync_sel* in register *config32*).
2. Sync the clock divider and FIFO pointers.
3. Verify there are no FIFO alarms either through register *config5* or through the ALARM pin.
4. Disable clock divider sync by setting *clkdiv_sync_ena* to “0” in register *config0*.

After these steps all the DAC34H84 outputs will be synchronized.

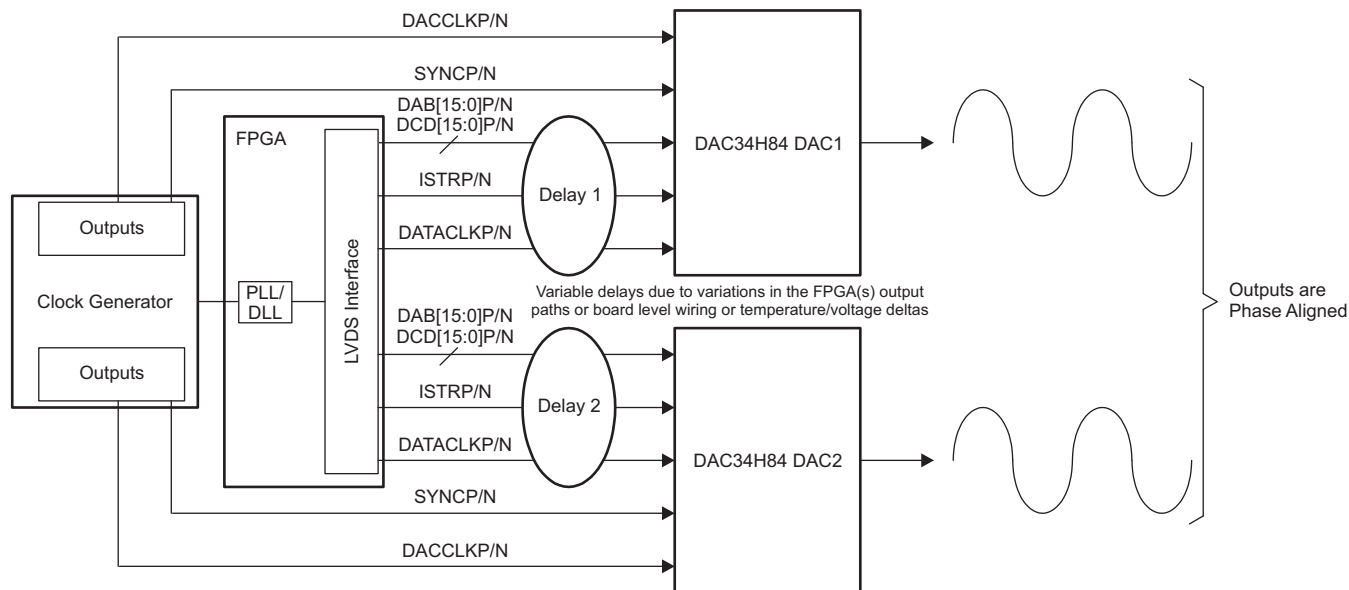
MULTI-DEVICE SYNCHRONIZATION: PLL ENABLED WITH DUAL SYNC SOURCE MODE

The DAC34H84 allows exact phase alignment between multiple devices even when operating with the internal PLL clock multiplier. In PLL clock mode, the PLL generates the DAC clock and an internal OSTR signal from the reference clock applied to the DACCLK inputs so there is no need to supply an additional LVPECL OSTR signal.

For this method to operate properly the SYNC signal should be set to reset the PLL N dividers to a known state by setting *pll_ndivsync_ena* in register *config24* to “1”. The SYNC signal resets the PLL N dividers with a rising edge, and the timing relationship $t_{s(SYNC_PLL)}$ and $t_{h(SYNC_PLL)}$ are relative to the reference clock presented on the DACCLK pin.

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Both SYNC and DACCLK can be set as low frequency signals to greatly simplifying trace routing (SYNC can be just a pulse as a single rising edge is required, if using a periodic signal it is recommended to clear the *pll_ndivsync_ena* bit after resetting the PLL dividers). Besides the $t_{s(\text{SYNC_PLL})}$ and $t_{h(\text{SYNC_PLL})}$ requirement between SYNC and DACCLK, there is no additional required timing relationship between the SYNC and ISTR signals or between DACCLK and DATACLK. The only restriction as in the PLL disabled case is that the DACCLK and SYNC signals are distributed from device to device with the lowest skew possible.



B0455-02

Figure 12. Synchronization System in Dual Sync Source Mode with PLL Enabled

The following steps are required to ensure the devices are fully synchronized. The procedure assumes all the DAC34H84 devices have a DACCLK and OSTR signal and must be carried out on each device.

1. Start-up the device as described in the power-up sequence. Set the DAC34H84 in Dual Sync Source mode and enable SYNC to reset the PLL dividers (set *pll_ndivsync_ena* in register *config24* to "1").
2. Reset the PLL dividers with a rising edge on SYNC.
3. Disable PLL dividers resetting.
4. Sync the clock divider and FIFO pointers.
5. Verify there are no FIFO alarms either through register *config5* or through the ALARM pin.
6. Disable clock divider sync by setting *clkdiv_sync_ena* to "0" in register *config0*.

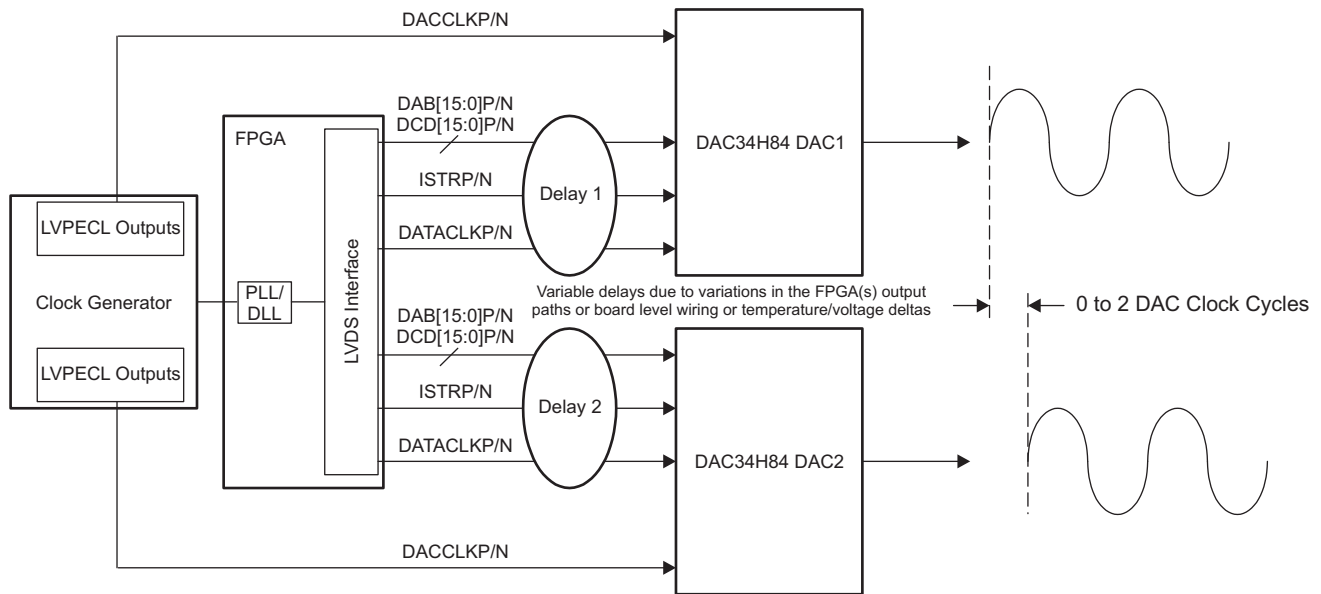
After these steps all the DAC34H84 outputs will be synchronized.

MULTI-DEVICE OPERATION: SINGLE SYNC SOURCE MODE

In Single Sync Source mode, the FIFO write and read pointers are reset from the same sync source, either ISTR or SYNC. Although the FIFO in this mode can still absorb the data delay differences due to variations in the digital source output paths or board level wiring it is impossible to guarantee data will be read from the FIFO of different devices simultaneously thus preventing exact phase alignment.

In Single Sync Source mode the FIFO read pointer reset is handoff between the two clock domains (DATACLK and FIFO OUT CLOCK) by simply re-sampling the write pointer reset. Since the two clocks are asynchronous there is a small but distinct possibility of a meta-stability during the pointer handoff. This meta-stability can cause the outputs of the multiple devices to slip by up to 2 DAC clock cycles.

When the PLL is enabled with Single Sync Source mode, the FIFO read pointer is not synchronized by the OSTR signal. Therefore, there is no restriction on the PLL PFD frequency as described in the previous section.



B0456-02

Figure 13. Multi-Device Operation in Single Sync Source Mode

FIR FILTERS

Figure 14 through Figure 17 show the magnitude spectrum response for the FIR0, FIR1, FIR2 and FIR3 interpolating filters where f_{IN} is the input data rate to the FIR filter. Figure 18 to Figure 21 show the composite filter response for 2x, 4x, 8x and 16x interpolation. The transition band for all interpolation settings is from 0.4 to 0.6 x f_{DATA} (the input data rate to the device) with < 0.001dB of pass-band ripple and > 90 dB stop-band attenuation.

The DAC34H84 also has a 9-tap inverse sinc filter (FIR4) that runs at the DAC update rate (f_{DAC}) that can be used to flatten the frequency response of the sample-and-hold output. The DAC sample-and-hold output sets the output current and holds it constant for one DAC clock cycle until the next sample, resulting in the well-known $\sin(x)/x$ or $\text{sinc}(x)$ frequency response (Figure 22, red line). The inverse sinc filter response (Figure 22, blue line) has the opposite frequency response from 0 to 0.4 x f_{DAC} , resulting in the combined response (Figure 22, green line). Between 0 to 0.4 x f_{DAC} , the inverse sinc filter compensates the sample-and-hold roll-off with less than 0.03 dB error.

The inverse sinc filter has a gain > 1 at all frequencies. Therefore, the signal input to FIR4 must be reduced from full scale to prevent saturation in the filter. The amount of back-off required depends on the signal frequency, and is set such that at the signal frequencies the combination of the input signal and filter response is less than 1 (0 dB). For example, if the signal input to FIR4 is at 0.25 x f_{DAC} , the response of FIR4 is 0.9 dB, and the signal must be backed off from full scale by 0.9 dB to avoid saturation. The gain function in the QMC blocks can be used to reduce the amplitude of the input signal. The advantage of FIR4 having a positive gain at all frequencies is that the user is then able to optimize the back-off of the signal based on its frequency.

The filter taps for all digital filters are listed in Table 4. Note that the loss of signal amplitude may result in lower SNR due to decrease in signal amplitude.

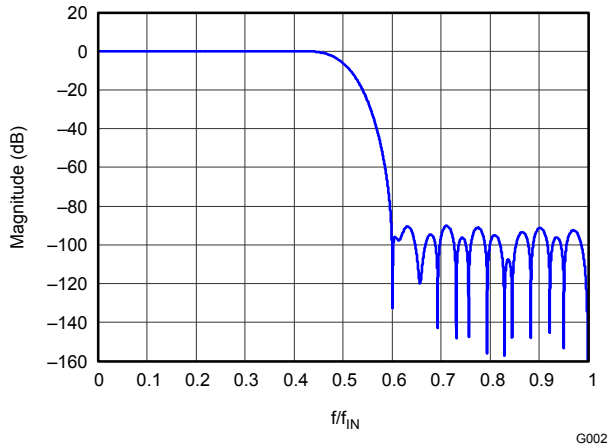


Figure 14. Magnitude Spectrum for FIR0

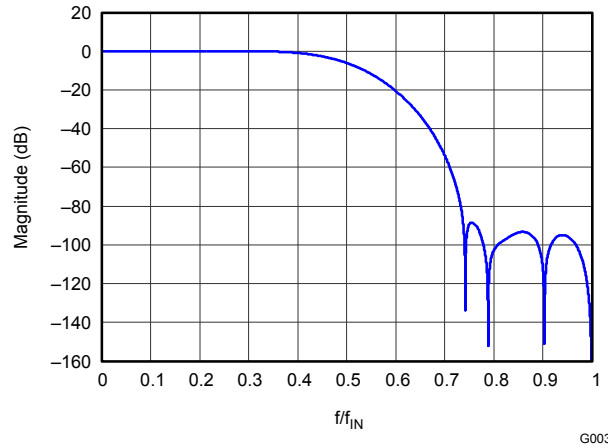


Figure 15. Magnitude Spectrum for FIR1

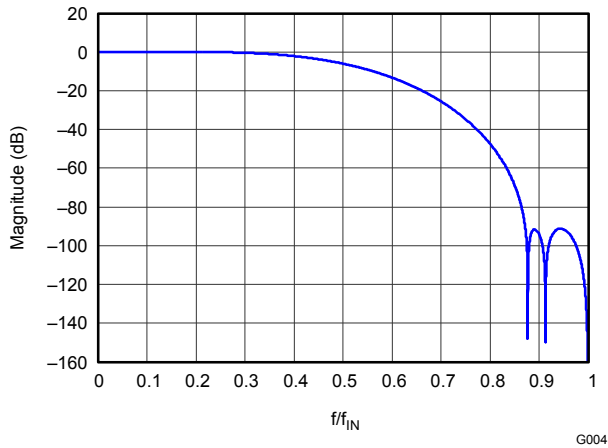


Figure 16. Magnitude Spectrum for FIR2

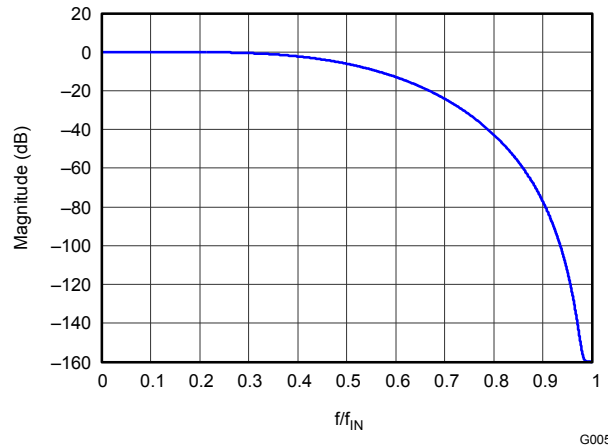


Figure 17. Magnitude Spectrum for FIR3

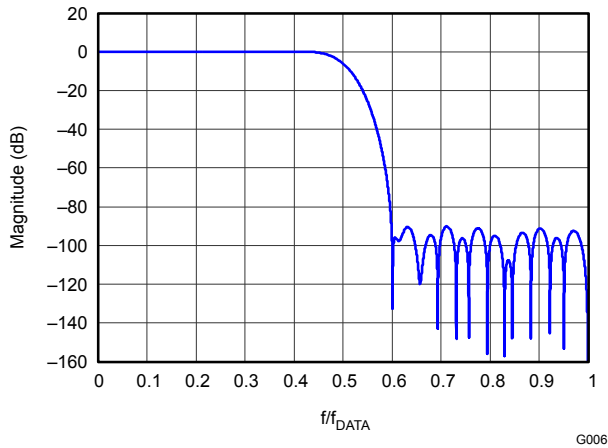


Figure 18. 2x Interpolation Composite Response

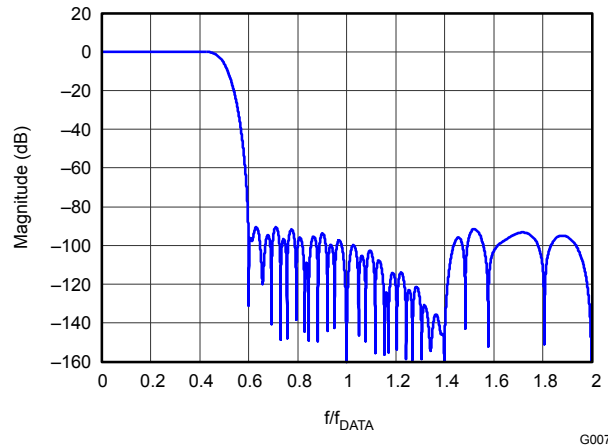


Figure 19. 4x Interpolation Composite Response

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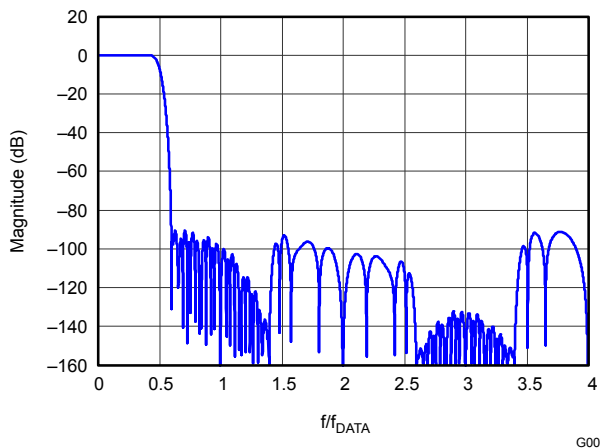


Figure 20. 8x Interpolation Composite Response

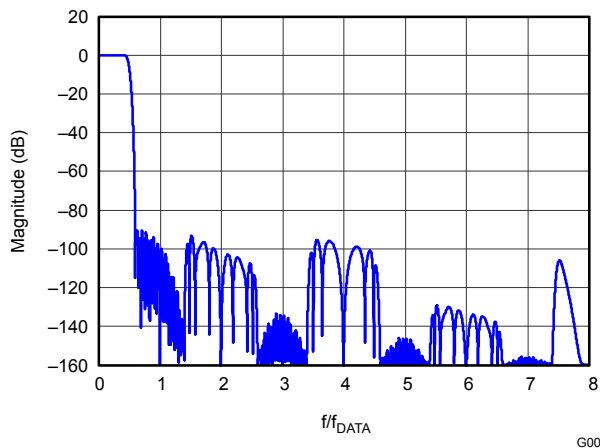


Figure 21. 16x Interpolation Composite Response

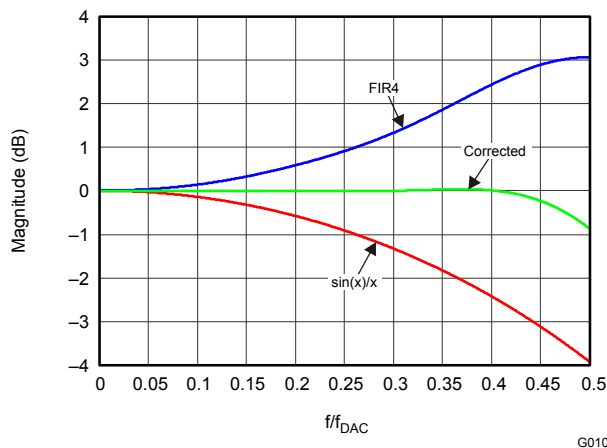


Figure 22. Magnitude Spectrum for Inverse Sinc Filter

Table 7. FIR Filter Coefficients

2x Interpolating Half-band Filters								Non-Interpolating Inverse-SINC Filter	
FIR0		FIR1		FIR2		FIR3		FIR4	
59 Taps		23 Taps		11 Taps		11 Taps		9 Taps	
6	6	-12	-12	29	29	3	3	1	1
0	0	0	0	0	0	0	0	-4	-4
-19	-19	84	84	-214	-214	-25	-25	13	13
0	0	0	0	0	0	0	0	-50	-50
47	47	-336	-336	1209	1209	150	150	592⁽¹⁾	
0	0	0	0	2048⁽¹⁾		256⁽¹⁾			
-100	-100	1006	1006						
0	0	0	0						
192	192	-2691	-2691						
0	0	0	0						
-342	-342	10141	10141						
0	0	16384⁽¹⁾							
572	572								
0	0								

(1) Center taps are highlighted in BOLD

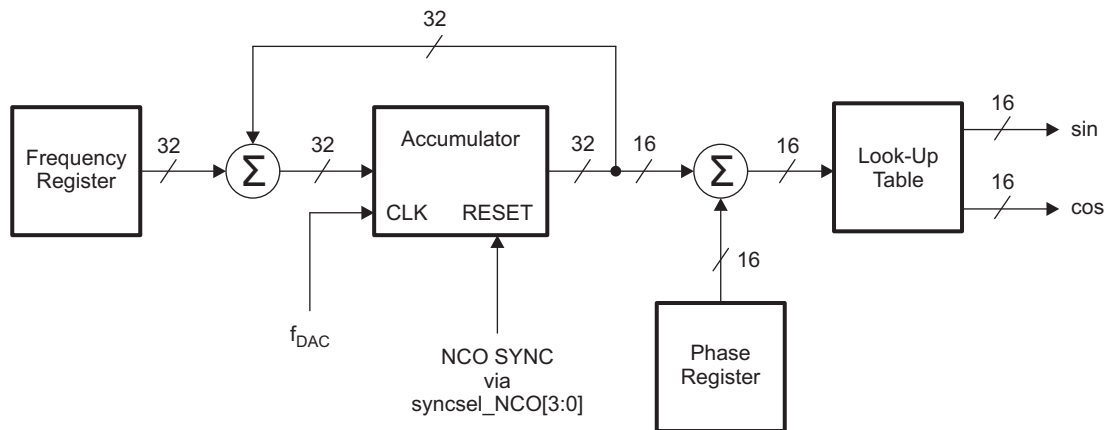
Table 7. FIR Filter Coefficients (continued)

2x Interpolating Half-band Filters				Non-Interpolating Inverse-SINC Filter					
FIR0		FIR1		FIR2		FIR3		FIR4	
59 Taps		23 Taps		11 Taps		11 Taps		9 Taps	
-914	-914								
0	0								
1409	1409								
0	0								
-2119	-2119								
0	0								
3152	3152								
0	0								
-4729	-4729								
0	0								
7420	7420								
0	0								
-13334	-13334								
0	0								
41527	41527								
65536⁽²⁾									

(2) Center taps are highlighted in BOLD

FULL COMPLEX MIXER

The DAC34H84 has two full complex mixer (FMIX) blocks with independent Numerically Controlled Oscillators (NCO) that enables flexible frequency placement without imposing additional limitations in the signal bandwidth. The NCOs have 32-bit frequency registers (*phaseaddAB(31:0)* and *phaseaddCD(31:0)*) and 16-bit phase registers (*phaseoffsetAB(15:0)* and *phaseoffsetCD(15:0)*) that generate the sine and cosine terms for the complex mixing. The NCO block diagram is shown in Figure 23.



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Figure 23. NCO Block Diagram

Synchronization of the NCOs occurs by resetting the NCO accumulators to zero. The synchronization source is selected by *syncsel_NCO(3:0)* in *config31*. The frequency word in the *phaseaddAB(31:0)* and *phaseaddCD(31:0)* registers is added to the accumulators every clock cycle, f_{DAC}. The output frequency of the NCO is:

$$f_{NCO} = \frac{freq \times f_{NCO_CLK}}{2^{32}} \tag{1}$$

Treating the two complex channels in the DAC34H84 as complex vectors of the form $I + j Q$, the output of FMIX $I_{OUT}(t)$ and $Q_{OUT}(t)$ is:

$$I_{OUT}(t) = (I_{IN}(t)\cos(2\pi f_{NCO}t + \delta) - Q_{IN}(t)\sin(2\pi f_{NCO}t + \delta)) \times 2^{(mixer_gain - 1)}$$

$$Q_{OUT}(t) = (I_{IN}(t)\sin(2\pi f_{NCO}t + \delta) + Q_{IN}(t)\cos(2\pi f_{NCO}t + \delta)) \times 2^{(mixer_gain - 1)}$$

where t is the time since the last resetting of the NCO accumulator, δ is the phase offset value and $mixer_gain$ is either 0 or 1. δ is given by:

$$\delta = 2\pi \times phase_offsetAB/CD(15:0)/2^{16}$$

The maximum output amplitude of FMIX occurs if $I_{IN}(t)$ and $Q_{IN}(t)$ are simultaneously full scale amplitude and the sine and cosine arguments are equal to $2\pi \times f_{NCO}t + \delta (2N-1) \times \pi/4$ ($N = 1, 2, \dots$).

With $mixer_gain = 0$ in *config2*, the gain through FMIX is $\sqrt{2}/2$ or -3 dB. This loss in signal power is in most cases undesirable, and it is recommended that the gain function of the QMC block be used to increase the signal by 3 dB to compensate. With $mixer_gain = 1$, the gain through FMIX is $\sqrt{2}$ or $+3$ dB, which can cause clipping of the signal if $I_{IN}(t)$ and $Q_{IN}(t)$ are simultaneously near full scale amplitude and should therefore be used with caution.

COARSE MIXER

In addition to the full complex mixer the DAC34H84 also has a coarse mixer block capable of shifting the input signal spectrum by the fixed mixing frequencies $\pm n \times f_s/8$. Using the coarse mixer instead of the full mixer will result in lower power consumption.

Treating the two complex channels as complex vectors of the form $I(t) + j Q(t)$, the outputs of the coarse mixer, $I_{OUT}(t)$ and $Q_{OUT}(t)$ are equivalent to:

$$I_{OUT}(t) = I(t)\cos(2\pi f_{CMIX}t) - Q(t)\sin(2\pi f_{CMIX}t)$$

$$Q_{OUT}(t) = I(t)\sin(2\pi f_{CMIX}t) + Q(t)\cos(2\pi f_{CMIX}t)$$

where f_{CMIX} is the fixed mixing frequency selected by *cmix(3:0)*. The mixing combinations are described in [Table 8](#).

Table 8. Coarse Mixer Combinations

cmix(3:0)	Fs/8 Mixer cmix(3)	Fs/4 Mixer cmix(2)	Fs/2 Mixer cmix(1)	-Fs/4 Mixer cmix(0)	Mixing Mode
0000	Disabled	Disabled	Disabled	Disabled	No mixing
0001	Disabled	Disabled	Disabled	Enabled	$-F_s/4$
0010	Disabled	Disabled	Enabled	Disabled	$F_s/2$
0100	Disabled	Enabled	Disabled	Disabled	$+F_s/4$
1000	Enabled	Disabled	Disabled	Disabled	$+F_s/8$
1010	Enabled	Disabled	Enabled	Disabled	$-3F_s/8$
1100	Enabled	Enabled	Disabled	Disabled	$+3F_s/8$
1110	Enabled	Enabled	Enabled	Disabled	$-F_s/8$
All others	–	–	–	–	Not recommended

QUADRATURE MODULATION CORRECTION (QMC)

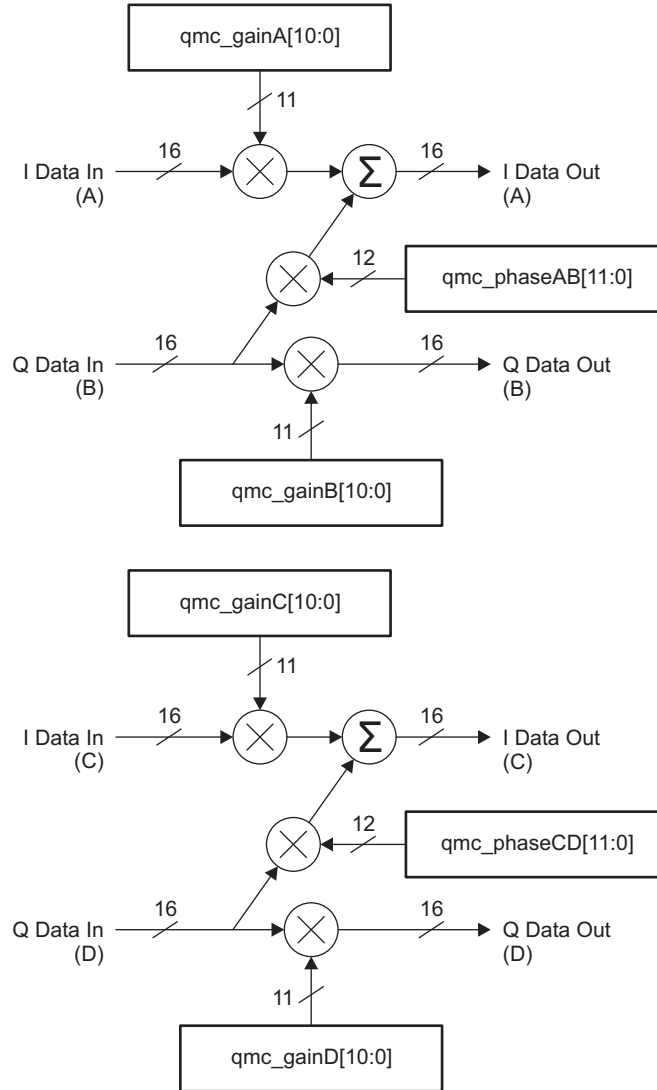
GAIN AND PHASE CORRECTION

The DAC34H84 includes a Quadrature Modulator Correction (QMC) block. The QMC blocks provide a mean for changing the gain and phase of the complex signals to compensate for any I and Q imbalances present in an analog quadrature modulator. The block diagram for the QMC block is shown in [Figure 24](#). The QMC block contains 3 programmable parameters.

Registers *qmc_gainA/B(10:0)* and *qmc_gainC/D(10:0)* controls the I and Q path gains and is an 11-bit unsigned value with a range of 0 to 1.9990 and the default gain is 1.0000. The implied decimal point for the multiplication is between bit 9 and bit 10.

Register *qmc_phaseAB/CD(11:0)* control the phase imbalance between I and Q and are a 12-bit values with a range of -0.5 to approximately 0.49975 . The QMC phase term is not a direct phase rotation but a constant that is multiplied by each "Q" sample then summed into the "I" sample path. This is an approximation of a true phase rotation in order to keep the implementation simple.

LO feed-through can be minimized by adjusting the DAC offset feature described below.



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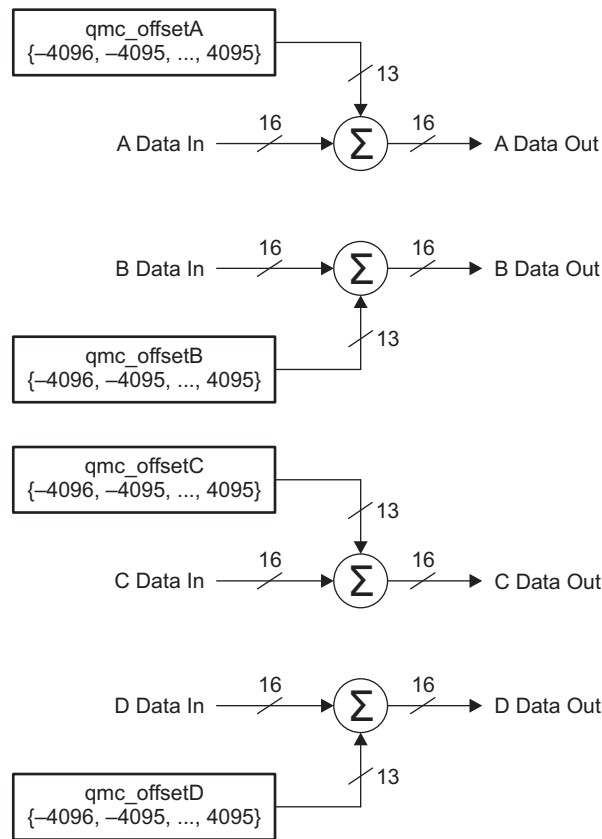
Figure 24. QMC Block Diagram

OFFSET CORRECTION

Registers *qmc_offsetA(12:0)*, *qmc_offsetB(12:0)*, *qmc_offsetC(12:0)* and *qmc_offsetD(12:0)* can be used to independently adjust the DC offsets of each channel. The offset values are in represented in 2s-complement format with a range from -4096 to 4095 .

The offset value adds a digital offset to the digital data before digital-to-analog conversion. Since the offset is added directly to the data it may be necessary to back off the signal to prevent saturation. Both data and offset values are LSB aligned.

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Figure 25. Digital Offset Block Diagram

GROUP DELAY CORRECTION

A complex transmitter system typically is consisted of a DAC, reconstruction filter network, and I/Q modulator. Besides the gain and phase mismatch contribution, there could also be timing mismatch contribution from each components. For instance, the timing mismatch could come from the PCB trace length variation between the I and Q channels and the group delay variation from the reconstruction filter.

This timing mismatch in the complex transmitter system creates phase mismatch that varies linearly with respect to frequency. To compensate for the I/Q imbalances due to this mismatch, the DAC34H84 has group delay correction block for each DAC channel. Each DAC channel can adjust its delay through *grp_delayI(7:0)* and *grp_delayQ(7:0)* in register *config46* and *config47*, respectively. The delay range is approximately 100ps over the 256 digital steps. The group delay correction, along with gain/phase correction, can be useful for correcting imbalances in wide-band transmitter system.

TEMPERATURE SENSOR

The DAC34H84 incorporates a temperature sensor block which monitors the temperature by measuring the voltage across 2 transistors. The voltage is converted to an 8-bit digital word using a successive-approximation (SAR) analog to digital conversion process. The result is scaled, limited and formatted as a twos complement value representing the temperature in degrees Celsius.

The sampling is controlled by the serial interface signals SDENB and SCLK. If the temperature sensor is enabled (*tsense_sleep* = "0" in register *config26*) a conversion takes place each time the serial port is written or read. The data is only read and sent out by the digital block when the temperature sensor is read in *tempdata(7:0)* in *config6*. The conversion uses the first eight clocks of the serial clock as the capture and conversion clock, the data is valid on the falling eighth SCLK. The data is then clocked out of the chip on the rising edge of the ninth SCLK. No other clocks to the chip are necessary for the temperature sensor operation. As a result the temperature sensor is enabled even when the device is in sleep mode.

In order for the process described above to operate properly, the serial port read from *config6* must be done with an SCLK period of at least 1 μ s. If this is not satisfied the temperature sensor accuracy is greatly reduced.

DATA PATTERN CHECKER

The DAC34H84 incorporates a simple pattern checker test in order to determine errors in the data interface. The main cause of failures is setup/hold timing issues. The test mode is enabled by asserting *iotest_ena* in register *config1*. In test mode the analog outputs are deactivated regardless of the state of TXENA or *sif_textnable* in register *config3*.

The data pattern key used for the test is 8 words long and is specified by the contents of *iotest_pattern[0:7]* in registers *config37* through *config44*. The data pattern key can be modified by changing the contents of these registers.

The first word in the test frame is determined by a rising edge transition in ISTR or SYNC, depending on the *syncsel_fifo(4:0)* setting in *config32*. At this transition, the *pattern0* word should be input to the data DAB[15:0] pins, and *pattern2* should be input to the data DCD[15:0] pins. Patterns 1, 4, and 5 of DAB[15:0] bus and pattern 3, 6, and 7 of DCD[15:0] bus should follow sequentially on each edge of DATACLK (rising and falling). The sequence should be repeated until the pattern checker test is disabled by setting *iotest_ena* back to “0”. It is not necessary to have a rising ISTR or SYNC edge aligned with every four DATACLK cycle, just the first one to mark the beginning of the series.

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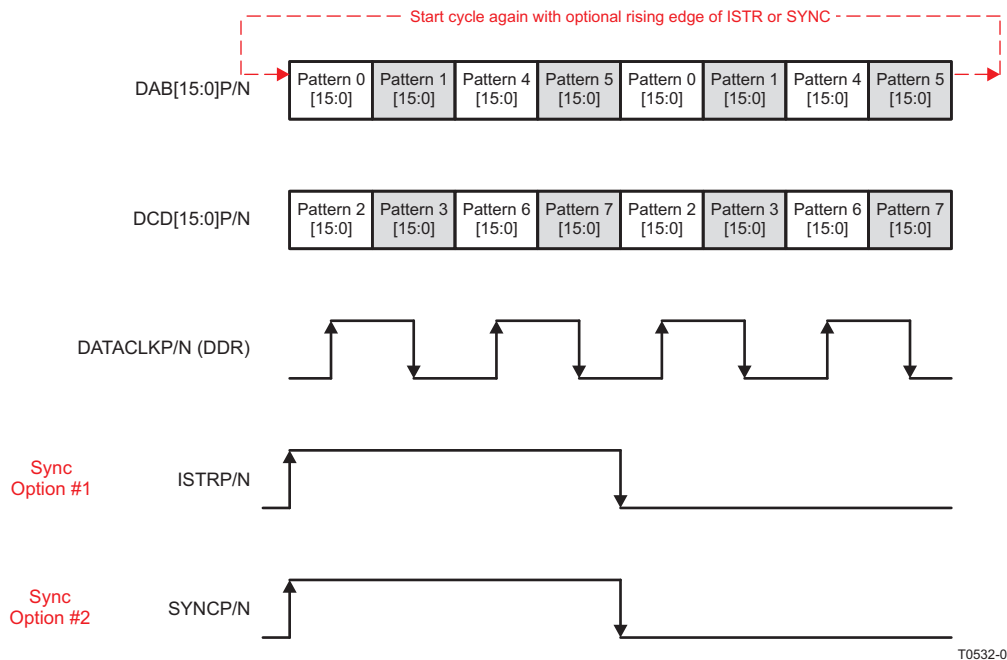
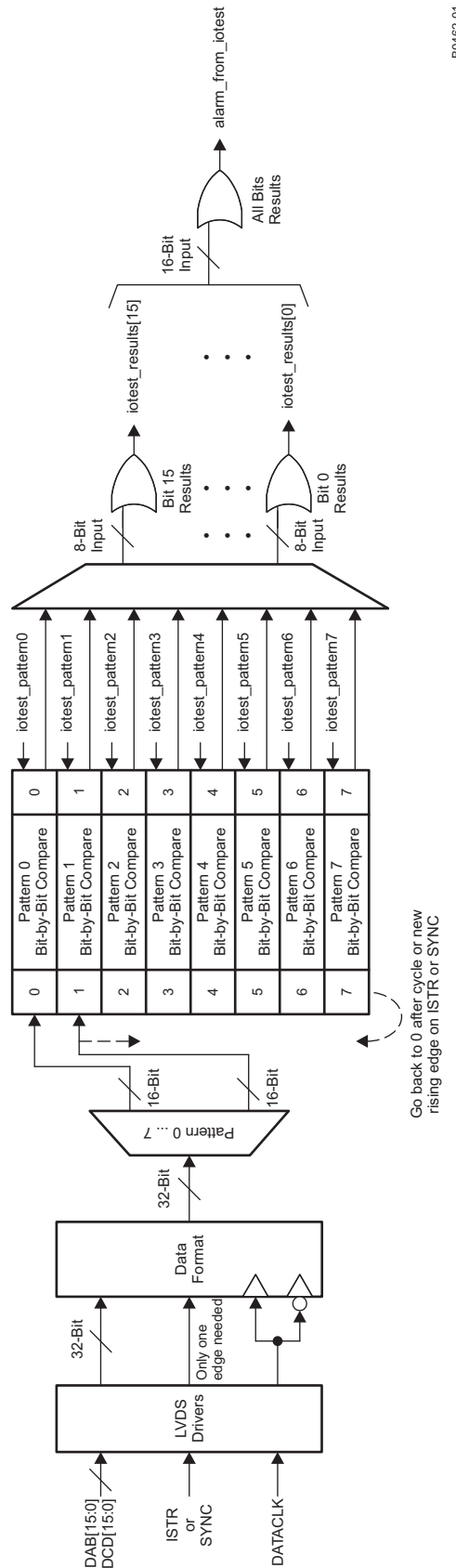


Figure 26. IO Pattern Checker Data Transmission Format

The test mode determines if the all the patterns on the two 16-bit LVDS data buses (DAB[15:0]P/N and DCD[15:0]P/N) were received correctly by comparing the received data against the data pattern key. If any bits in either of the two 16-bit data buses were received incorrectly, the corresponding bits in *iotest_results(15:0)* in register *config4* will be set to “1” to indicate bit error location. The user can check the corresponding bit location on both 16-bit data buses and implement the fix accordingly. Furthermore, the error condition will trigger the *alarm_from_iotest* bit in register *config5* to indicate a general error in the data interface.

For instance, *pattern0* is programmed to the default of 0x7A7A. If the received Pattern 0 is 0x7A7B, then bit 0 in *iotest_results(15:0)* will be set to “1” to indicate an error in bit 0 location. The *alarm_from_iotest* will also be set to “1” to report the data transfer error. Note that *iotest_results(15:0)* does not indicate which of the 16-bit buses has the error. The user needs to check both 16-bit buses and then narrow down the error from the bit location information.



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Figure 27. DAC34H84 Pattern Check Block Diagram

The alarms can be cleared by writing 0x0000 to *iotest_results(15:0)* and “0” to *alarm_from_iotest* through the serial interface. The serial interface will read back 0s if there are no errors or if the errors are cleared. The corresponding alarm bit will remain a “1” if the errors remain.

It is recommended to enable the pattern checker and then run the pattern sequence for 100 or more complete cycles before clearing the *iotest_results(15:0)* and *alarm_from_iotest*. This will eliminate the possibility of false alarms generated during the setup sequence.

PARITY CHECK TEST

The DAC34H84 has a parity check test that enables continuous validity monitoring of the data received by the DAC. Parity check testing in combination with the data pattern checker offer an excellent solution for detecting board assembly issues due to missing pad connections.

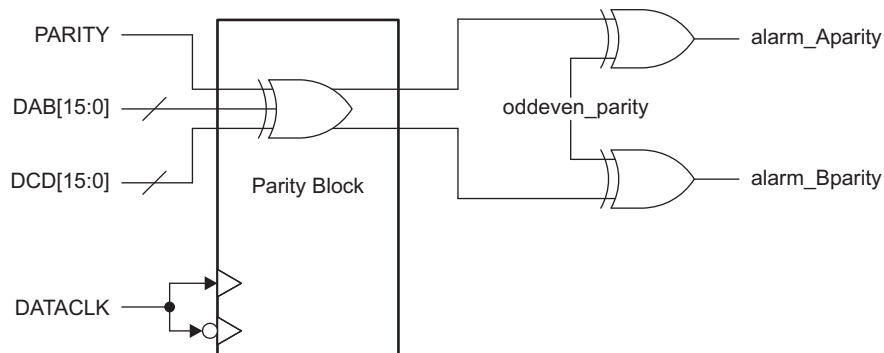
For the parity check test, an extra parity bit is added to the data bits to ensure that the total number of set bits (bits with value 1) is even or odd. This simple scheme is used to detect single or any other odd number of data transfer errors. Parity testing is implemented in the DAC34H84 in two ways: 32-bit parity and dual 16-bit parity.

32-BIT PARITY

In the 32-bit mode the additional parity bit is sourced to the parity input (PARITYP/N) for the 32-bit data transfer into the DAB[15:0]P/N and DCD[15:0]P/N inputs. This mode is enabled by setting the *single_parity_ena* bit in register *config1*. The input parity value is defined to be the total number of logic 1s on the 33-bit data bus – the DAB[15:0]P/N inputs, the DCD[15:0]P/N inputs, and the PARITYP/N input. This value, the total number of logic 1s, must match the parity test selected in the *oddeven_parity* bit in register *config1*.

For example, if the *oddeven_parity* bit is set to “1” for odd parity, then the number of 1s on the 33-bit data bus should be odd. The DAC will check the data transfer through the parity input. If the data received has odd number of 1s, then the parity is correct. If the data received has even number of 1s, then the parity is incorrect. The corresponding alarm for parity error will be set accordingly.

Figure 28 shows the simple XOR structure used to check word parity. Parity is tested independently for data captured on both rising and falling edges of DATACLK (*alarm_Aparity* and *alarm_Bparity*, respectively). Testing on both edges helps in determining a possible setup/hold issue. Both alarms are captured individually in register *config5*.



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Figure 28. DAC34H84 32-Bit Parity Check

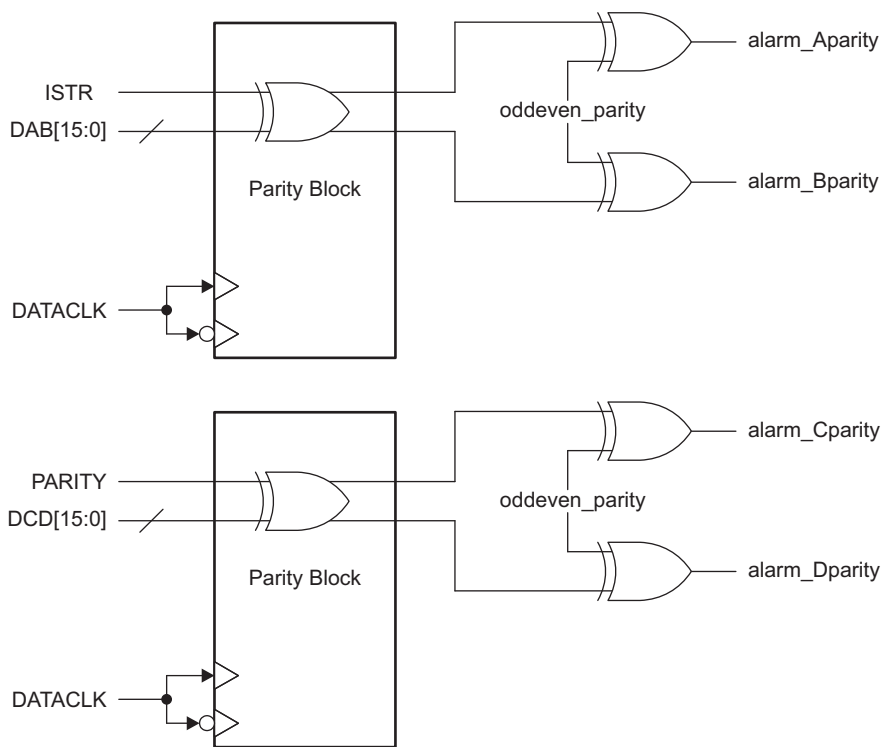
DUAL 16-BIT PARITY

In the dual 16-bit mode, each 16-bit LVDS data bus input will be accompanied by a parity bit for error checking. The DAB[15:0]P/N and ISTRP/N are one 17-bit data path, and the DCD[15:0]P/N and PARITYP/N are another path. This mode is enabled by setting the *dual_parity_ena* bit in register *config1*. The input parity value is defined to be the total number of logic 1s on each 17-bit data bus. This value, the total number of logic 1s, must match the parity test selected in the *oddeven_parity* bit in register *config1*.

For example, if the `oddeven_parity` bit is set to “1” for odd parity, then the number of 1s on each 17-bit data bus should be odd. The DAC will check the data transfer through the parity input. If the data received has odd number of 1s, then the parity is correct. If the data received has even number of 1s, then the parity is incorrect. The corresponding alarm for parity error will be set accordingly.

Figure 29 shows the simple XOR structure used to check word parity. Parity is tested independently for data captured on both rising and falling edges of `DATACLK` for each data path (`alarm_Aparity`, `alarm_Bparity`, `alarm_Cparity`, and `alarm_Dparity`, respectively). Testing on both edges and both data buses helps in determining a possible setup/hold issue. All of the alarms are captured individually in register `config5`.

In this mode the `ISTR` signal functions as a parity signal and cannot be used to sync the FIFO pointer simultaneously. It is recommended to use the `SYNC` to sync the FIFO pointer. If `ISTR` has to be used to sync the FIFO pointer, the `ISTR` sync can only be possible upon start-up when dual 16-bit parity function is disabled. Once the initialization is finished, disable the FIFO pointer sync through `ISTR` (by configuring `syncsel_fifoin` and `syncsel_fifoout` in `config32`) and enable the dual 16-bit parity function afterwards.



B0463-01

Figure 29. DAC34H84 Dual 16-Bit Parity Check

DAC34H84 ALARM MONITORING

The DAC34H84 includes a flexible set of alarm monitoring that can be used to alert of a possible malfunction scenario. All the alarm events can be accessed either through the `config5` register or through the `ALARM` pin. Once an alarm is set, the corresponding alarm bit in register `config5` must be reset through the serial interface to allow further testing. The set of alarms includes the following conditions:

Zero check alarm

- `Alarm_from_zerochk`. Occurs when the FIFO write pointer has an all zeros pattern. Since the write pointer is a shift register, all zeros will cause the input point to be stuck until the next sync event. When this happens a sync to the FIFO block is required.

FIFO alarms

- `alarm_from_fifo`. Occurs when there is a collision in the FIFO pointers or a collision event is close.
 - `alarm_fifo_2away`. Pointers are within two addresses of each other.

- alarm_fifo_1away. Pointers are within one address of each other.
- alarm_fifo_collision. Pointers are equal to each other.

Clock alarms

- clock_gone. Occurs when either the DACCLK or DATALOCK have been stopped.
 - alarm_dacclk_gone. Occurs when the DACCLK has been stopped.
 - alarm_dataclk_gone. Occurs when the DATACLK has been stopped.

Pattern checker alarm

- alarm_from_iotest. Occurs when the input data pattern does not match the pattern key.

PLL alarm

- alarm_from_pll. Occurs when the PLL is out of lock.

Parity alarms

- alarm_Aparity: In dual parity mode, alarm indicating a parity error on the A word. In single parity mode, alarm on the 32-bit data captured on the rising edge of DATACLKP/N.
- alarm_Bparity: In dual parity mode, alarm indicating a parity error on the B word. In single parity mode, alarm on the 32-bit data captured on the falling edge of DATACLKP/N.
- alarm_Cparity: In dual parity mode, alarm indicating a parity error on the C word.
- alarm_Dparity: In dual parity mode, alarm indicating a parity error on the D word.

To prevent unexpected DAC outputs from propagating into the transmit channel chain, the clock and alarm_fifo_collision alarms can be set in *config2* to shut-off the DAC output automatically regardless of the state of TXENA or *sif_txenable*.

Alarm monitoring is implemented as follows:

- Power up the device using the recommended power-up sequence.
- Clear all the alarms in *config5* by setting them to 0.
- Unmask those alarms that will generate a hardware interrupt through the ALARM pin in *config7*.
- Enable automatic DAC shut-off in register *config2* if required.
- In the case of an alarm event, the ALARM pin will trigger. If automatic DAC shut-off has been enabled the DAC outputs will be disabled.
- Read registers *config5* to determine which alarm triggered the ALARM pin.
- Correct the error condition and re-synchronize the FIFO.
- Clear the alarms in *config5*.
- Re-read *config5* to ensure the alarm event has been corrected.
- Keep clearing and reading *config5* until no error is reported.

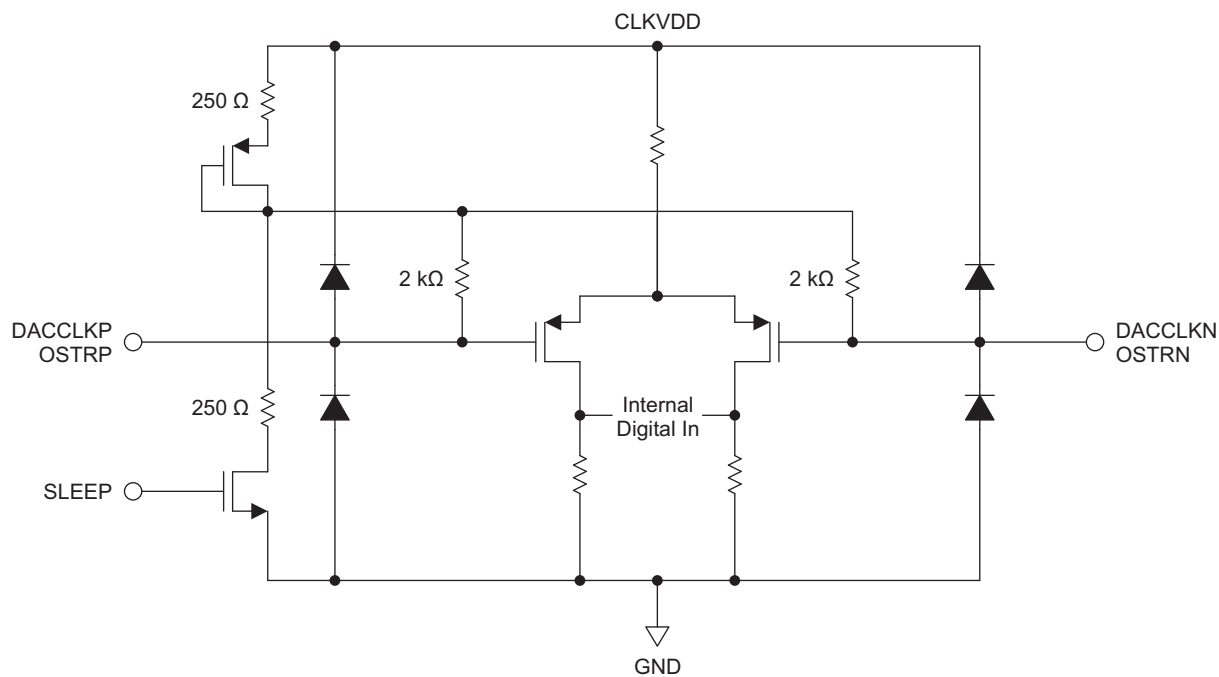
POWER-UP SEQUENCE

The following startup sequence is recommended to power-up the DAC34H84:

- Set TXENA low
- Supply all 1.2V voltages (DACVDD, DIGVDD, CLKVDD and VFUSE) and all 3.3V voltages (AVDD, IOVDD, PLLAVDD and REFAVDD). The 1.2V and 3.3V supplies can be powered up simultaneously or in any order. There are no specific requirements on the ramp rate for the supplies.
- Provide all LVPECL inputs: DACCLKP/N and if used OSTRP/N.
- Toggle the RESETB pin for a minimum 25 ns active low pulse width.
- Program the SIF registers.
- Provide all LVDS inputs (DAB[15:0]P/N, DCD[15:0]P/N, DATACLKP/N, ISTRP/N, SYNCNCP/N and PARITYP/N) simultaneously.
- Sync the clock dividers and FIFO. After an ISTRP/N low-to-high transition, clock divider syncing can be disabled by setting *clkdiv_sync_ena* (*config0*, bit 2) to 0. Optionally, disable FIFO syncing by setting *syncsel_fifoout(4:0)* and *syncsel_fifoout(4:0)* to “0000” after initialization.
- Enable transmit of data by asserting the TXENA pin or set *sif_txenable* to “1”.

LVPECL INPUTS

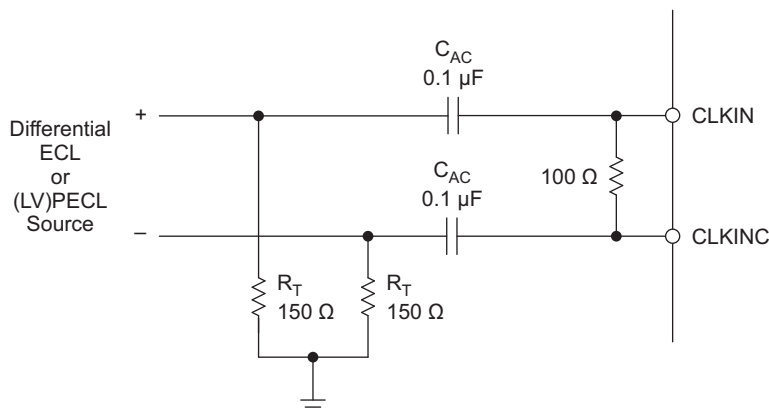
Figure 30 shows an equivalent circuit for the DAC input clock (DACCLKP/N) and the output strobe clock (OSTRP/N).



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Figure 30. DACCLKP/N and OSTRP/N Equivalent Input Circuit

Figure 31 shows the preferred configuration for driving the CLKIN/CLKINC input clock with a differential ECL/PECL source.



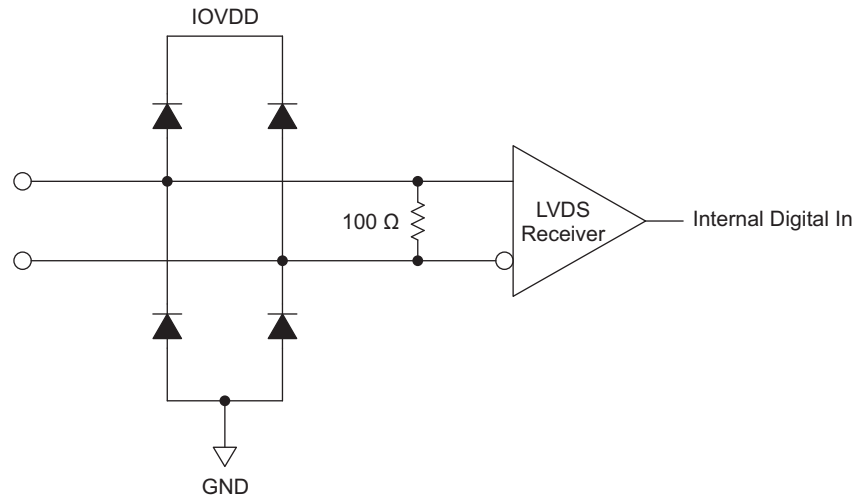
S0029-02

Figure 31. Preferred Clock Input Configuration with a Differential ECL/PECL Clock Source

PRODUCT PREVIEW

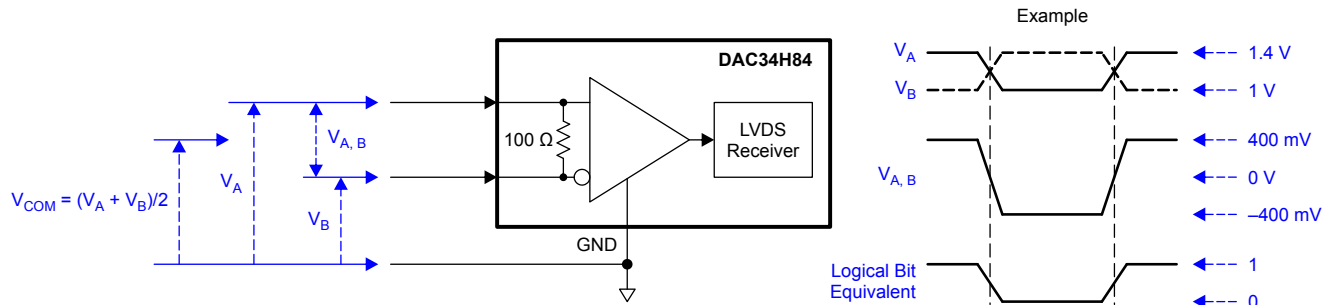
LVDS INPUTS

The DAB[15:0]P/N, DCD[15:0]P/N, DATACLKP/N, SYNCN/P, PARITYP/N, and ISTRP/N LVDS pairs have the input configuration shown in Figure 32. Figure 33 shows the typical input levels and common-mode voltage used to drive these inputs.



S0516-01

Figure 32. DAB[15:0]P/N, DCD[15:0]P/N, DATACLKP/N, ISTRP/N, SYNCN/P and PARITYP/N LVDS Input Configuration



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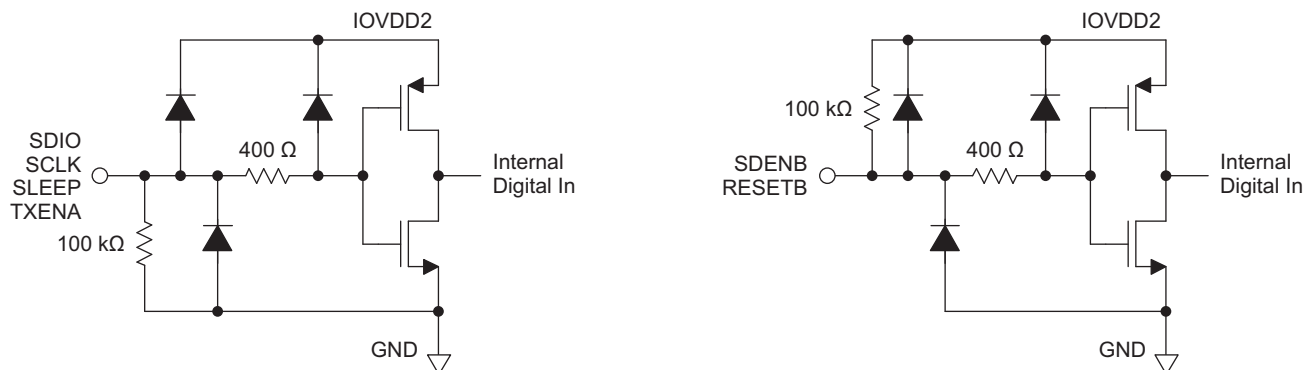
Figure 33. LVDS Data Input Levels

Table 9. Example LVDS Data Input Levels

Applied Voltages		Resulting Differential Voltage	Resulting Common-Mode Voltage	Logical Bit Binary Equivalent
VA	VB	VA,B	VCOM	
1.4 V	1.0 V	400 mV	1.2 V	1
1.0 V	1.4 V	-400 mV		0
1.2 V	0.8 V	400 mV	1.0 V	1
0.8 V	1.2 V	-400 mV		0

CMOS DIGITAL INPUTS

Figure 34 shows a schematic of the equivalent CMOS digital inputs of the DAC34H84. SDIO, SCLK, SLEEP and TXENA have pull-down resistors while SDENB and RESETB have pull-up resistors internal to the DAC34H84. All the CMOS digital inputs and outputs are referred to the IOVDD2 supply, which can vary from 1.8V to 3.3V. This facilitates the I/O interface and eliminates the need of level translation. See the specification table for logic thresholds. The pull-up and pull-down circuitry is approximately equivalent to 100kΩ.



S0027-04

Figure 34. CMOS Digital Equivalent Input

REFERENCE OPERATION

The DAC34H84 uses a bandgap reference and control amplifier for biasing the full-scale output current. The full-scale output current is set by applying an external resistor R_{BIAS} to pin BIASJ. The bias current I_{BIAS} through resistor R_{BIAS} is defined by the on-chip bandgap reference voltage and control amplifier. The default full-scale output current equals 64 times this bias current and can thus be expressed as:

$$I_{OUT_{FS}} = 64 \times I_{BIAS} = 64 \times (V_{EXTIO} / R_{BIAS}) / 2$$

The DAC34H84 has a 4-bit coarse gain control *coarse_dac(3:0)* in the *config3* register. Using gain control, the $I_{OUT_{FS}}$ can be expressed as:

$$I_{OUT_{FS}} = (coarse_dac + 1)/16 \times I_{BIAS} \times 64 = (coarse_dac + 1)/16 \times (V_{EXTIO} / R_{BIAS}) / 2 \times 64$$

where V_{EXTIO} is the voltage at terminal EXTIO. The bandgap reference voltage delivers an accurate voltage of 1.2V. This reference is active when *extref_ena* = '0' in *config27*. An external decoupling capacitor C_{EXT} of 0.1 μ F should be connected externally to terminal EXTIO for compensation. The bandgap reference can additionally be used for external reference operation. In that case, an external buffer with high impedance input should be applied in order to limit the bandgap load current to a maximum of 100 nA. The internal reference can be disabled and overridden by an external reference by setting the *extref_ena* control bit. Capacitor C_{EXT} may hence be omitted. Terminal EXTIO thus serves as either input or output node.

The full-scale output current can be adjusted from 30 mA down to 10 mA by varying resistor R_{BIAS} or changing the externally applied reference voltage.

DAC TRANSFER FUNCTION

The CMOS DACs consist of a segmented array of PMOS current sources, capable of sourcing a full-scale output current up to 30 mA. Differential current switches direct the current to either one of the complementary output nodes IOU TP or IOU TN. Complementary output currents enable differential operation, thus canceling out common mode noise sources (digital feed-through, on-chip and PCB noise), dc offsets, even order distortion components, and increasing signal output power by a factor of two.

The full-scale output current is set using external resistor R_{BIAS} in combination with an on-chip bandgap voltage reference source (+1.2 V) and control amplifier. Current I_{BIAS} through resistor R_{BIAS} is mirrored internally to provide a maximum full-scale output current equal to 64 times I_{BIAS} .

The relation between IOU TP and IOU TN can be expressed as:

$$I_{OUT_{FS}} = I_{OUTP} + I_{OUTN}$$

We will denote current flowing into a node as – current and current flowing out of a node as + current. Since the output stage is a current source the current flows from the IOU_{TP} and IOU_{TN} pins. The output current flow in each pin driving a resistive load can be expressed as:

$$I_{OUTP} = I_{OUT_{FS}} \times \text{CODE} / 65536$$

$$I_{OUTN} = I_{OUT_{FS}} \times (65535 - \text{CODE}) / 65536$$

where CODE is the decimal representation of the DAC data input word

For the case where IOU_{TP} and IOU_{TN} drive resistor loads R_L directly, this translates into single ended voltages at IOU_{TP} and IOU_{TN}:

$$V_{OUTP} = I_{OUT1} \times R_L$$

$$V_{OUTN} = I_{OUT2} \times R_L$$

Assuming that the data is full scale (65535 in offset binary notation) and the R_L is 25 Ω , the differential voltage between pins IOU_{TP} and IOU_{TN} can be expressed as:

$$V_{OUTP} = 20\text{mA} \times 25 \Omega = 0.5 \text{ V}$$

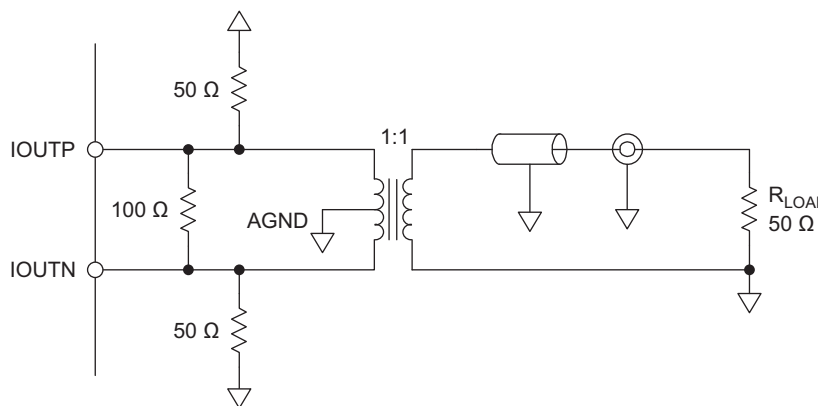
$$V_{OUTN} = 0\text{mA} \times 25 \Omega = 0 \text{ V}$$

$$V_{DIFF} = V_{OUTP} - V_{OUTN} = 0.5\text{V}$$

Note that care should be taken not to exceed the compliance voltages at node IOU_{TP} and IOU_{TN}, which would lead to increased signal distortion.

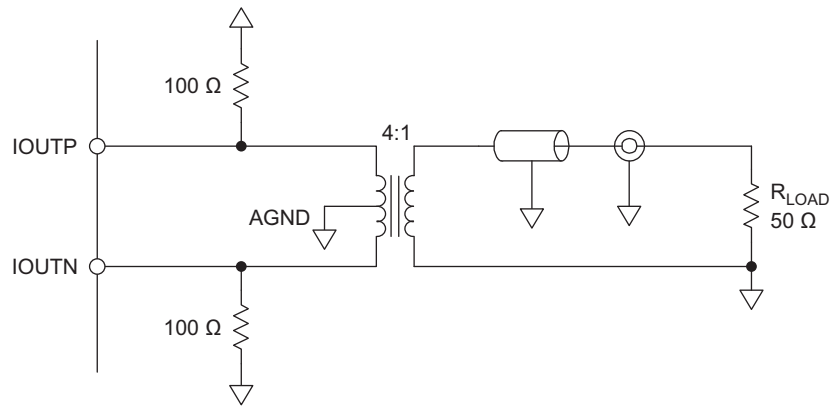
ANALOG CURRENT OUTPUTS

The DAC34H84 can be easily configured to drive a doubly terminated 50 Ω cable using a properly selected RF transformer. Figure 35 and Figure 36 show the 50 Ω doubly terminated transformer configuration with 1:1 and 4:1 impedance ratio, respectively. Note that the center tap of the primary input of the transformer has to be grounded to enable a DC current flow. Applying a 20 mA full-scale output current would lead to a 0.5 V_{pp} for a 1:1 transformer and a 1 V_{pp} output for a 4:1 transformer. The low dc-impedance between IOU_{TP} or IOU_{TN} and the transformer center tap sets the center of the ac-signal to GND, so the 1 V_{pp} output for the 4:1 transformer results in an output between –0.5 V and +0.5 V.



S0517-01

Figure 35. Driving a Doubly Terminated 50 Ω Cable Using a 1:1 Impedance Ratio Transformer



S0518-01

Figure 36. Driving a Doubly Terminated 50 Ω Cable Using a 4:1 Impedance Ratio Transformer

PRODUCT PREVIEW

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